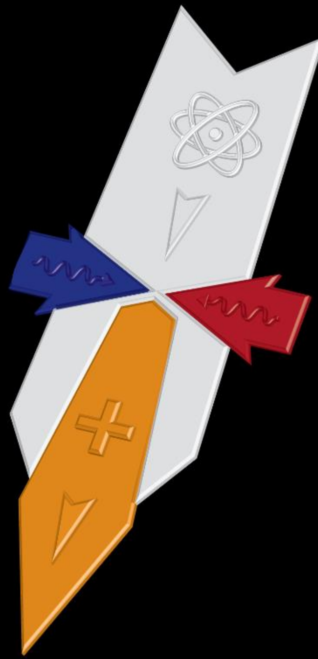
ZEROK NANOTECH

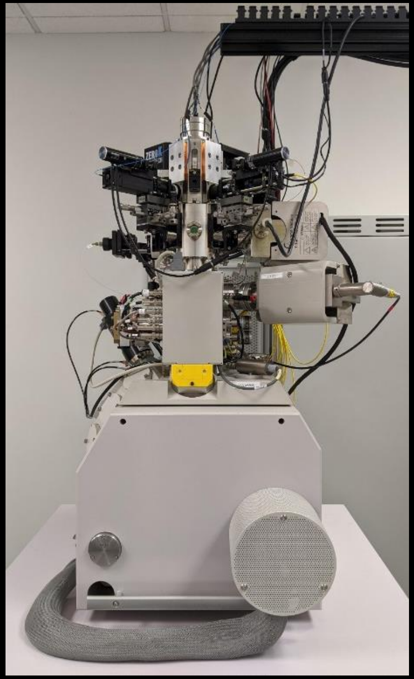
High-Resolution FIB and SIMS with the Cesium Low Temperature Ion Source (LoTIS)

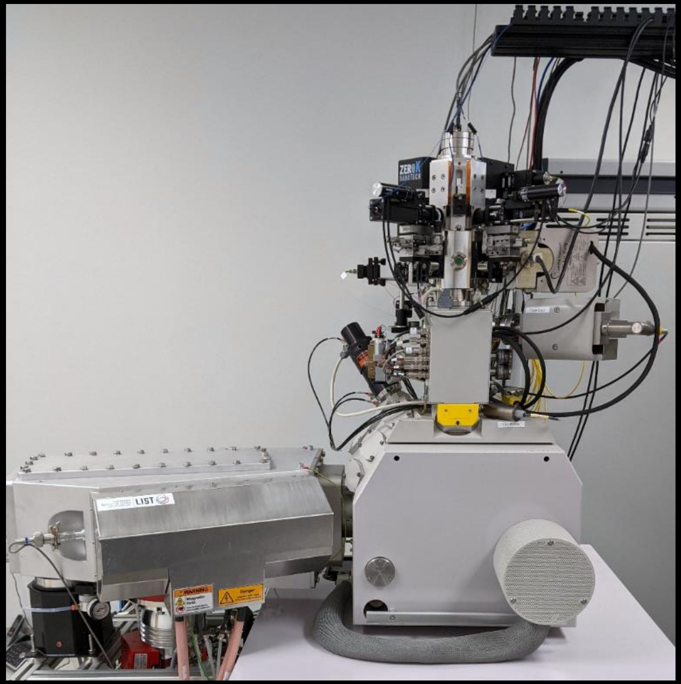
Adam V Steele, zeroK NanoTech
Brenton Knuffman, zeroK

adam@zeroK.com

Technology and Applications







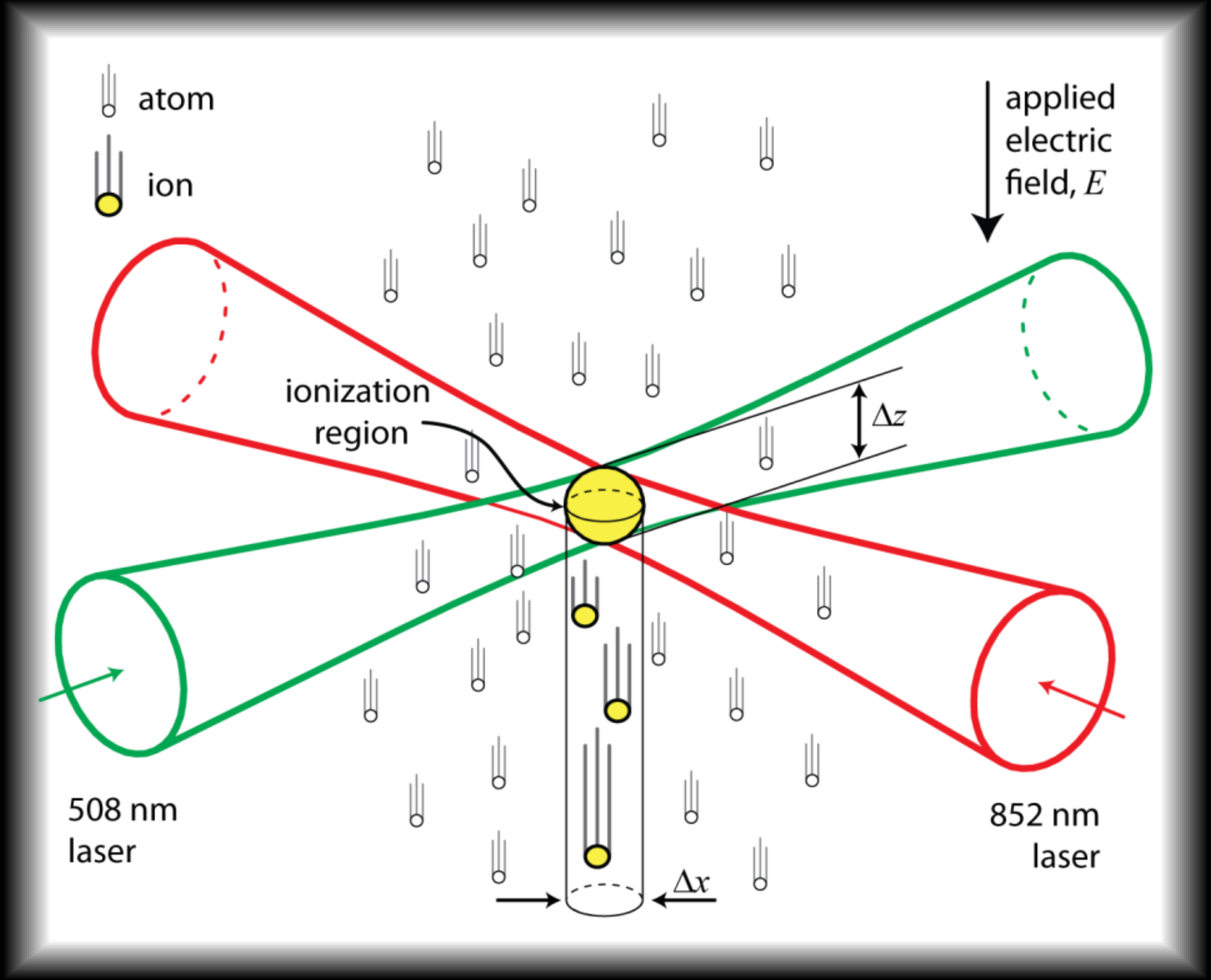
Cs$^+$ LoTIS	FIB:ZERO	SIMS:ZERO

• Low Temperature Ion Source
  • Laser-cooling + Photoionization
• Heavy ion nanomachining
• Small spot sizes
• Excellent resolution at low energy (~2 nm resolution at 1 pA, 16 kV)
• 1 pA - 10 nA
	• LoTIS + FIB
	• Comparable to standard Ga$^+$ FIB, with 2x higher resolution at low beam currents
	• Compatible with normal peripherals, gas chemistries etc..
		• FIB:ZERO with SIMS
		  • Analysis of secondary ions in a mass spectrometer
		• Best for elemental-compositional analysis
		• Collab. with Luxembourg Institute of Science and Technology (LIST)

How does LoTIS work?

Ions are created in a laser-cooled atomic beam as it flows through the intersection of photoionizing laser beams

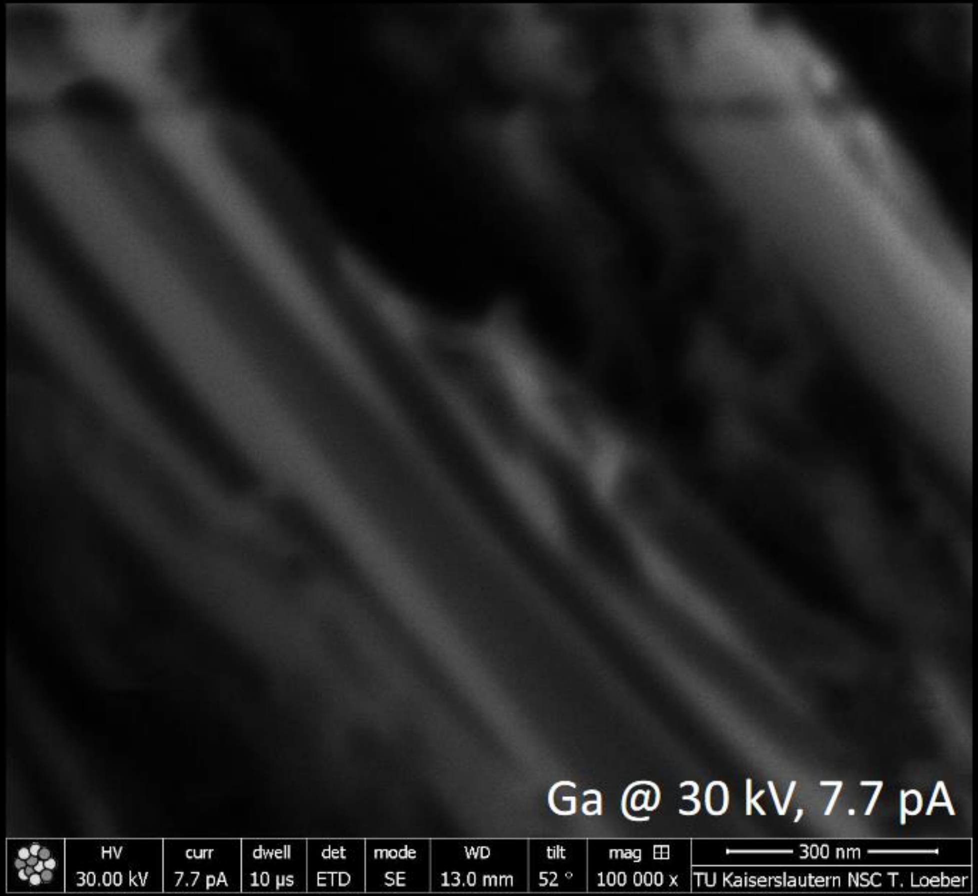
The cold temperature (~10 μK) is the key to achieving finely focused beams



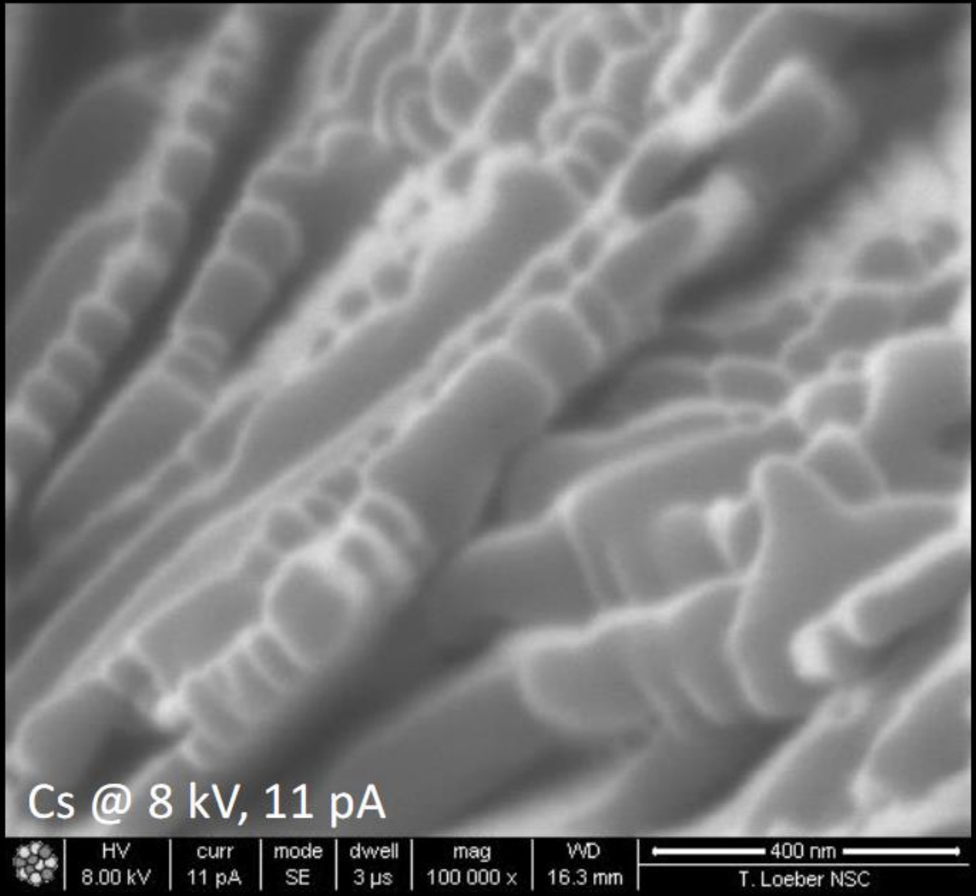
FIB:ZERO

Resolution

Ga ion image



Cs ion image

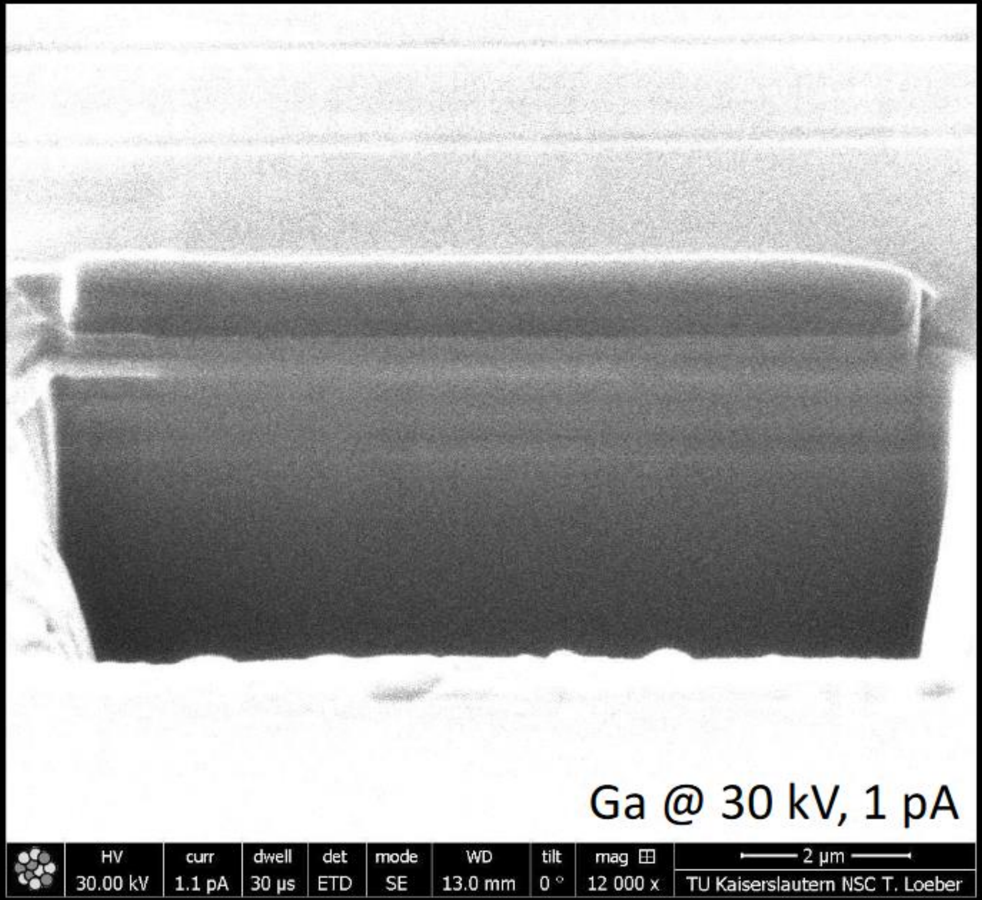


graphite pen: magnification 100k

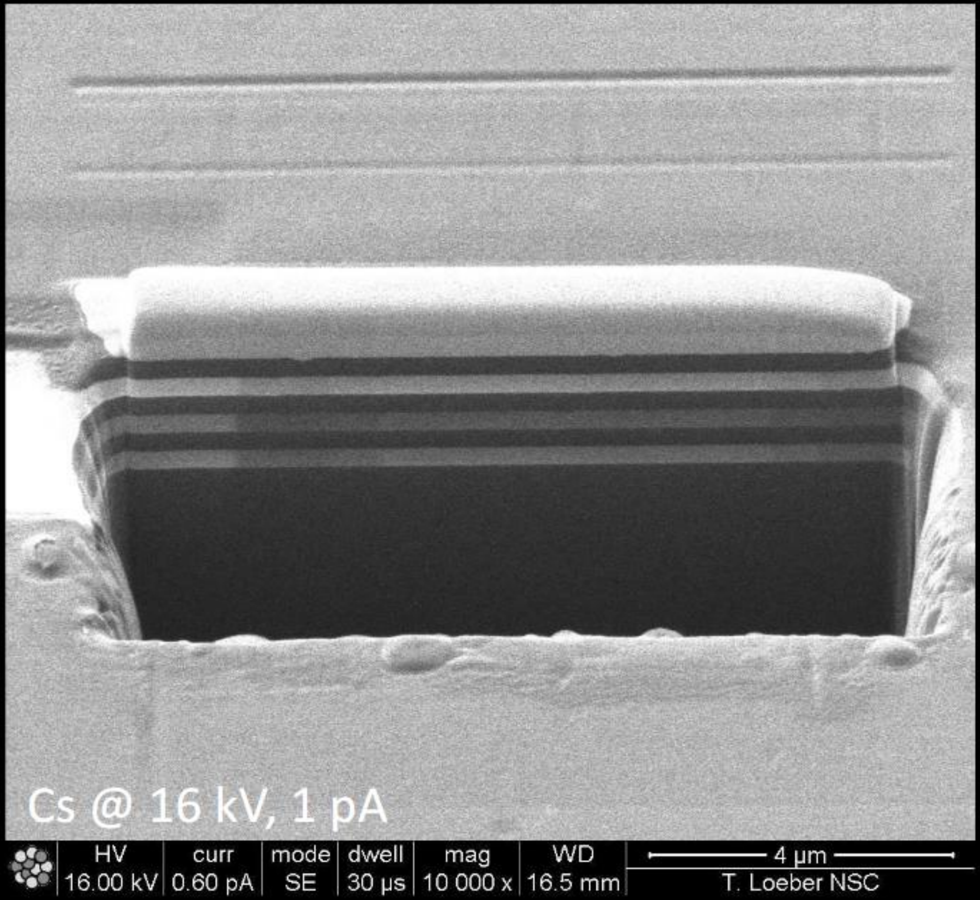
Data by T. Lober, presented at Micro and Nano Engineering Conference (MNE) 2023

Material contrast

Ga ion image



Cs ion image



Pt layer contrast of Ga inverted to Cs: dark <-> light

Data by T. Lober, presented at Micro and Nano Engineering Conference (MNE) 2023

FIB:ZERO Milling Rates

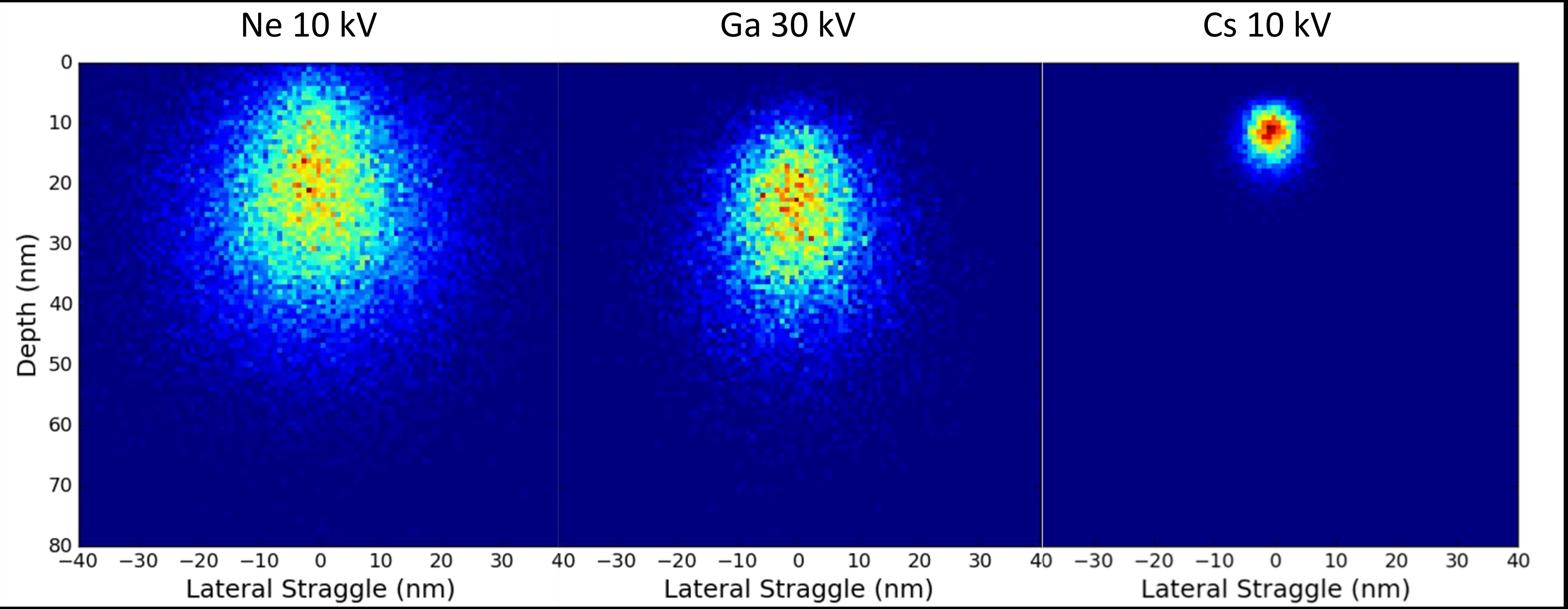
Milling rate of 10 kV Cs^+ FIB:ZERO about 15% lower than 30 kV Ga^+ for Si

Cs^+ LoTIS milling rates 90% higher than Ne^+ (and **much** higher than He^+)

Ne 10 kV	Ga 30 kV	Cs 10 kV
1.00-1.38 at/ion	2.20-2.40 at/ion	1.90-2.15 at/ion

Implant Depth Comparisons (SRIM simulation)

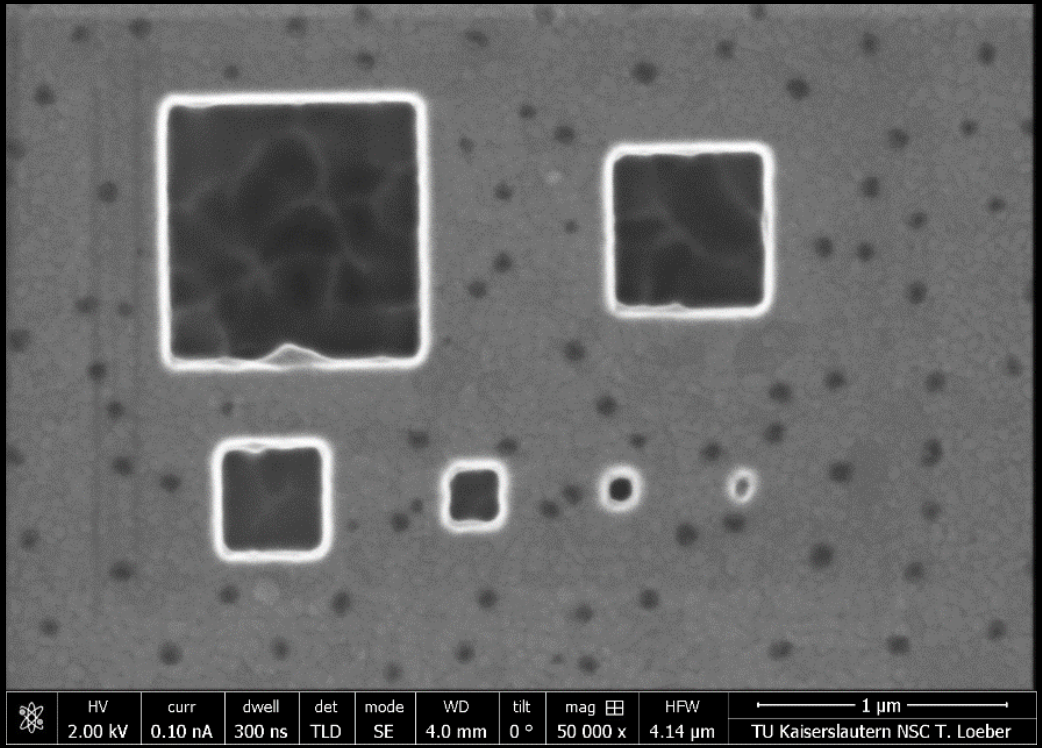
- Comparison of three scenarios where spot size might be ‘good enough’
- Cs has significantly reduced straggle and implant depth



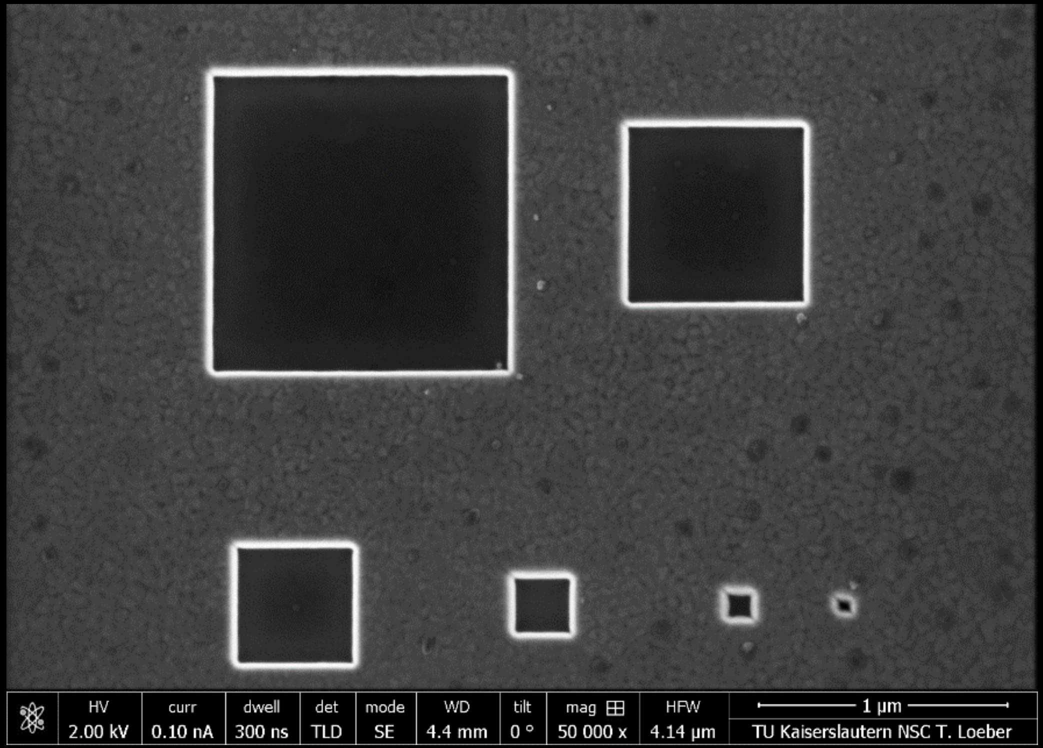
Milling Accuracy: 110 nm Au on Si

→ LoTIS provides clean mill boxes with sharp corners

Milled with Ga^+ LMIS



Milled with Cs^+ LoTIS



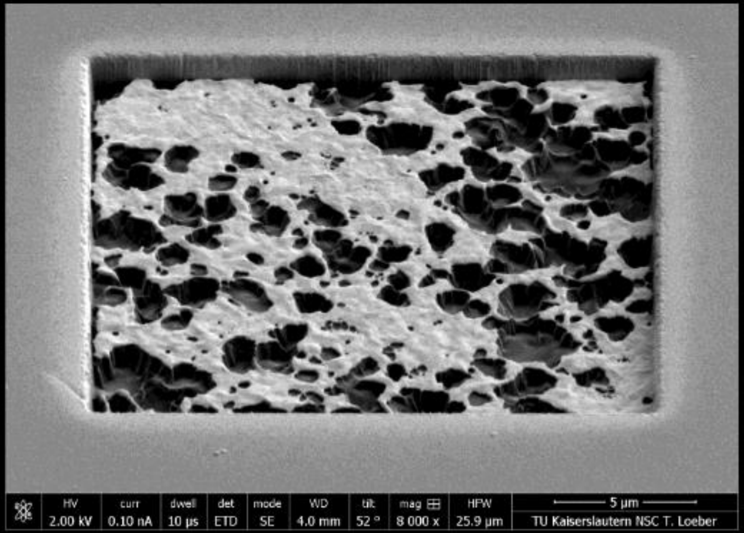
- squares with 1, 0.6, 0.4, 0.2, 0.1 and 0.05 µm length
- milled through the Au layer
- milling time Ga and Cs almost the same

Rheinland-Pfälzische Technische Universität Kaiserslautern Landau

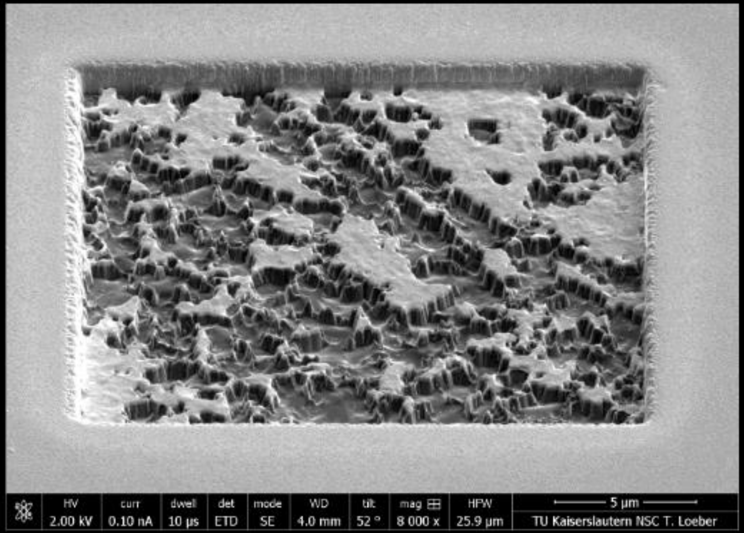
PHYSIK

Milling in Copper

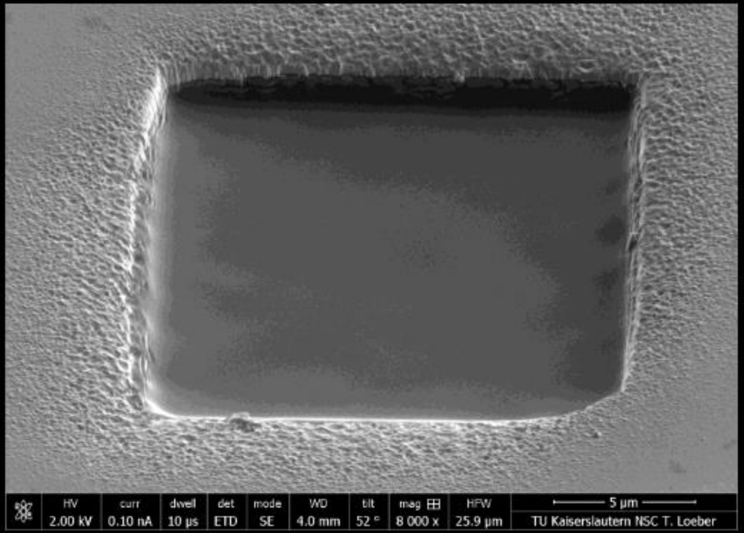
Ga ion: 30 kV @ 2640 pA



Ga ion: 16 kV @ 1440 pA



Cs ion: 16 kV @ 1070 pA

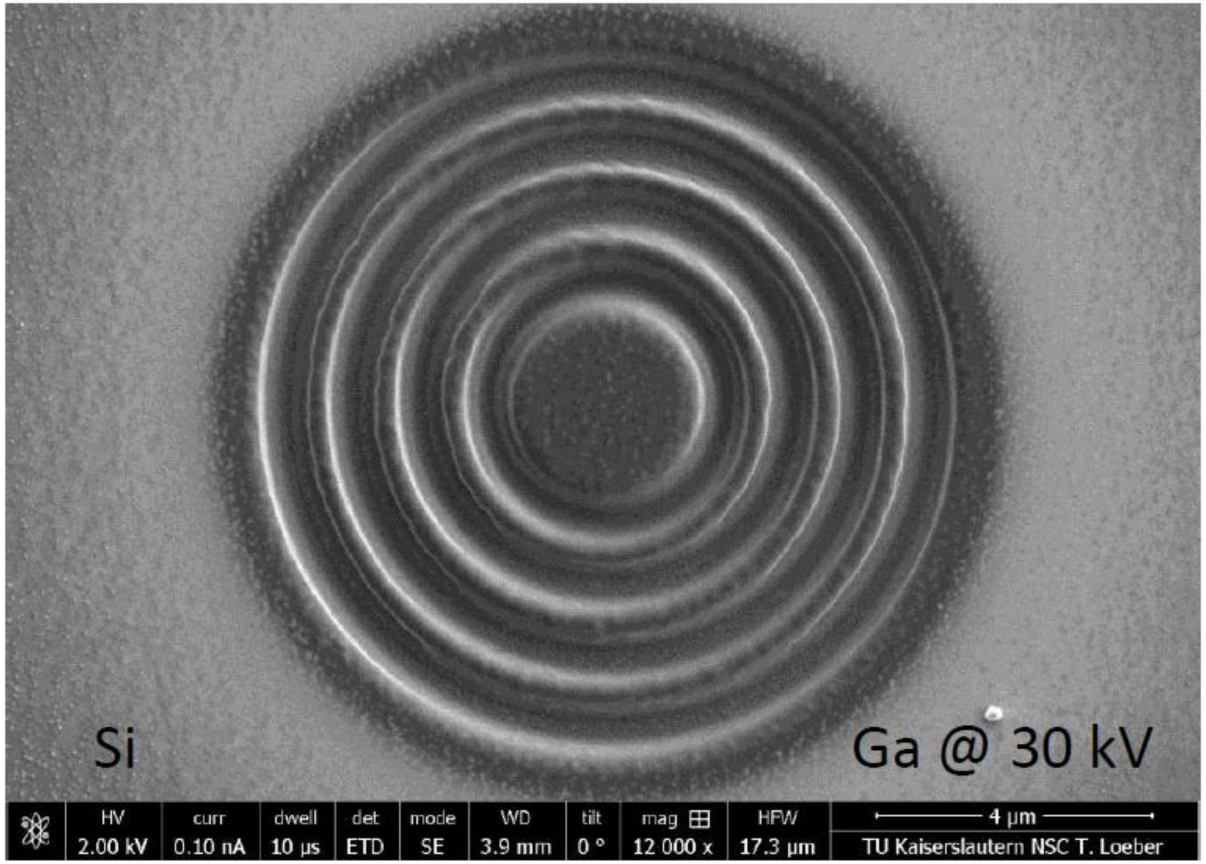


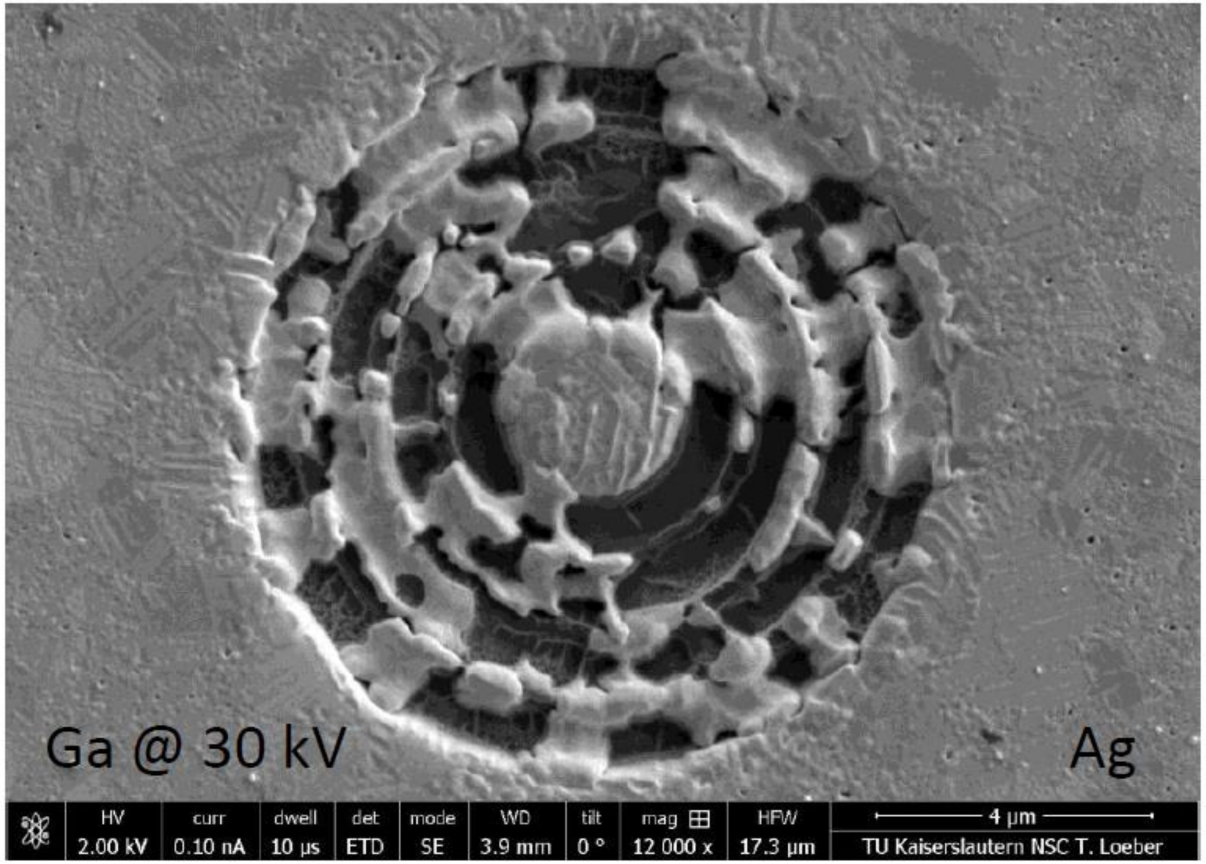
- sputtered Copper layer on Silicon
- layer thickness 1150 nm
- rectangle 20 µm x 20 µm
- milling time about 20 min
- dose about 4500 pC/µm^2

NSC

Data by T. Lober, presented at Micro and Nano Engineering Conference (MNE) 2023

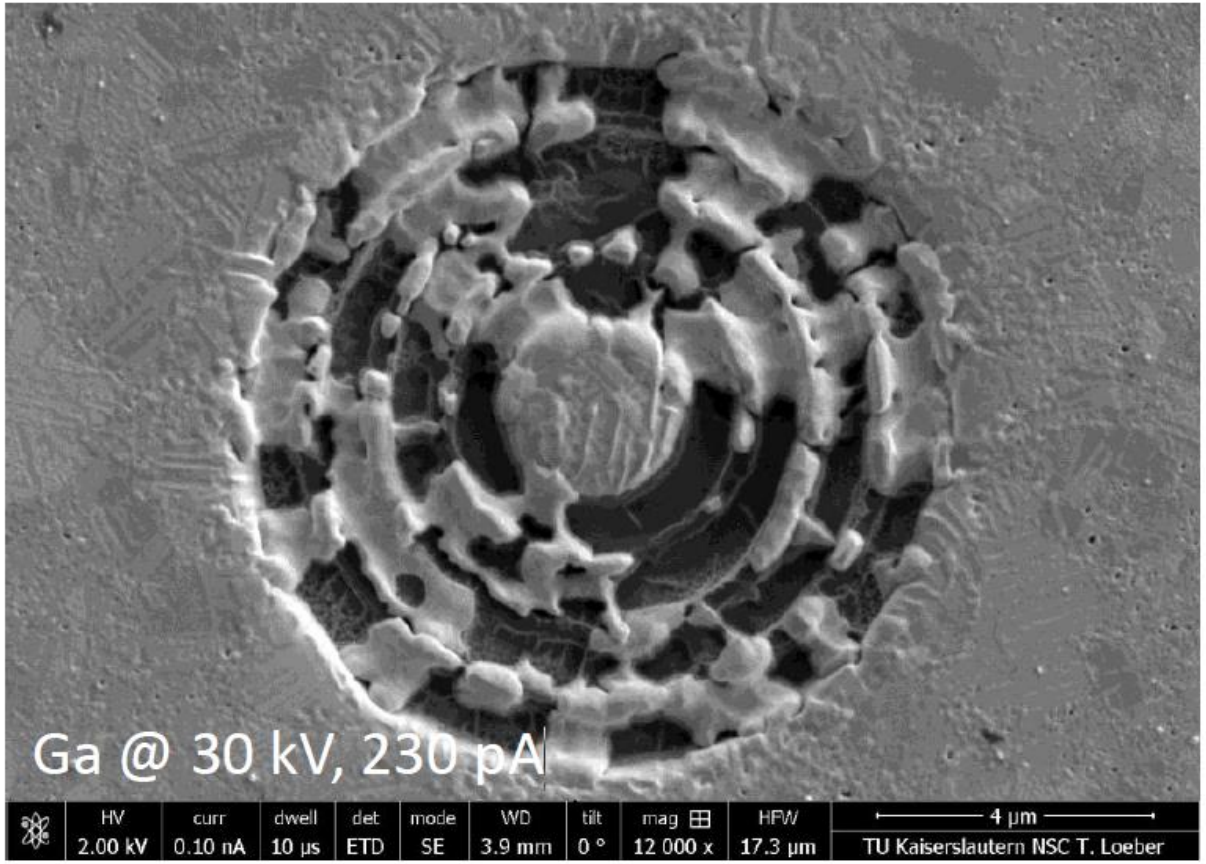
Milling in silver

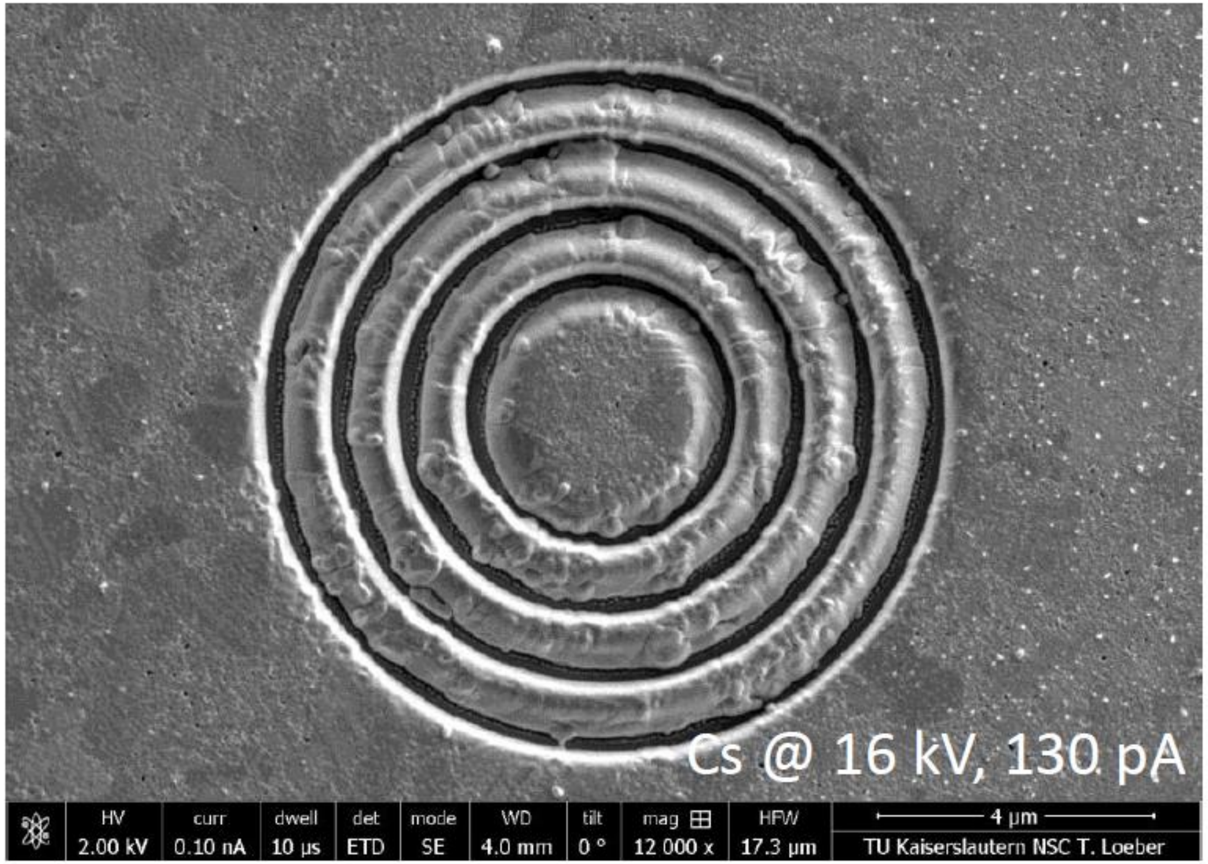




- demonstration: plasmonic ring structures
- no problem in silicon
- inhomogeneous milling in polycrystalline silver

Milling in silver





- plasmonic structures
- Ga: inhomogeneous milling in polycrystalline silver
- Cs: significant better rings

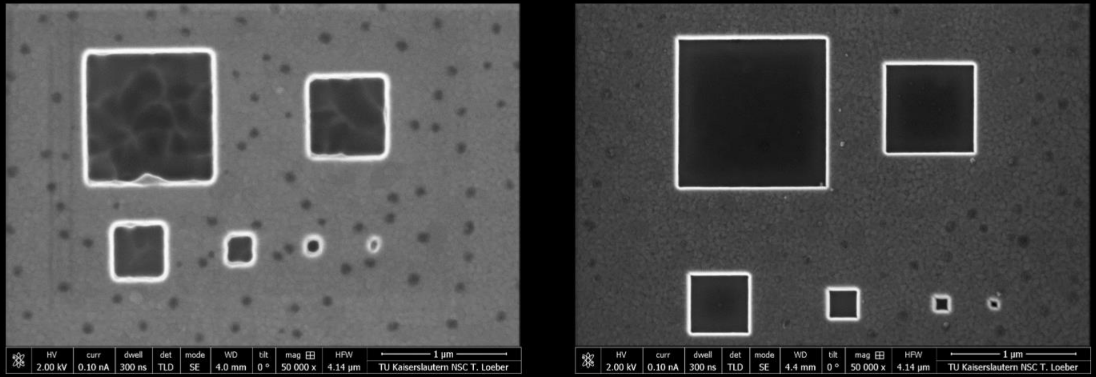
Summary- FIB:ZERO

- High resolution FIB nanomachining tool
- … with a Cs^+ ion source
- … excellent at milling small structures
- … demo tool available for collaborations
- … compatible with depo & etch gas chemistries
- … available as a FIB-SEM (Thermo-Fisher SCIOS)

Milling Accuracy: 110 nm Au on Si

→ LoTIS provides clean mill boxes with sharp corners

Milled with Ga^+ LMIS — Milled with Cs^+ LoTIS



- squares with 1, 0.6, 0.4, 0.2, 0.1 and 0.05 µm length
- milled through the Au layer
- milling time Ga and Cs almost the same

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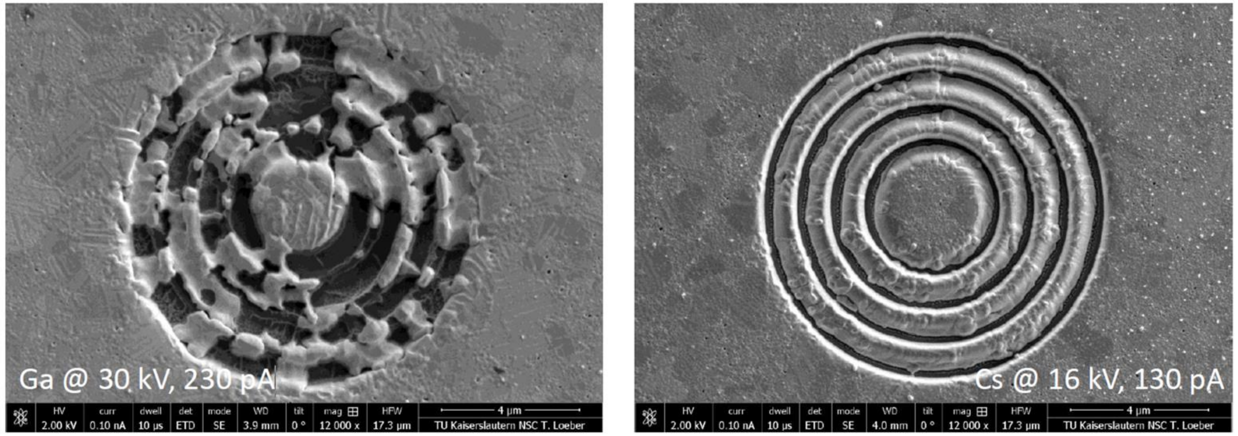
PHYSIK

Milling in silver



- plasmonic structures
- Ga: inhomogeneous milling in polycrystalline silver
- Cs: significant better rings

Existing Elemental Analysis Techniques and a New Solution

EDX/EELS

- Long sample-prep times
- 3D analysis infeasible
- Low-Z elements challenging

Site-Specific SIMS

- Resolution limited to ~50 nm with high yield (CAMECA NanoSIMS), or
- Can get a high resolution FIB (Ga, He, Ne) with a time-of-flight SIMS analyzer. But low secondary ion yields from these beams usually results in poor lateral resolution. Additionally, time-of-flight analyzers necessitate **long** acquisition times.

These points are addressable by

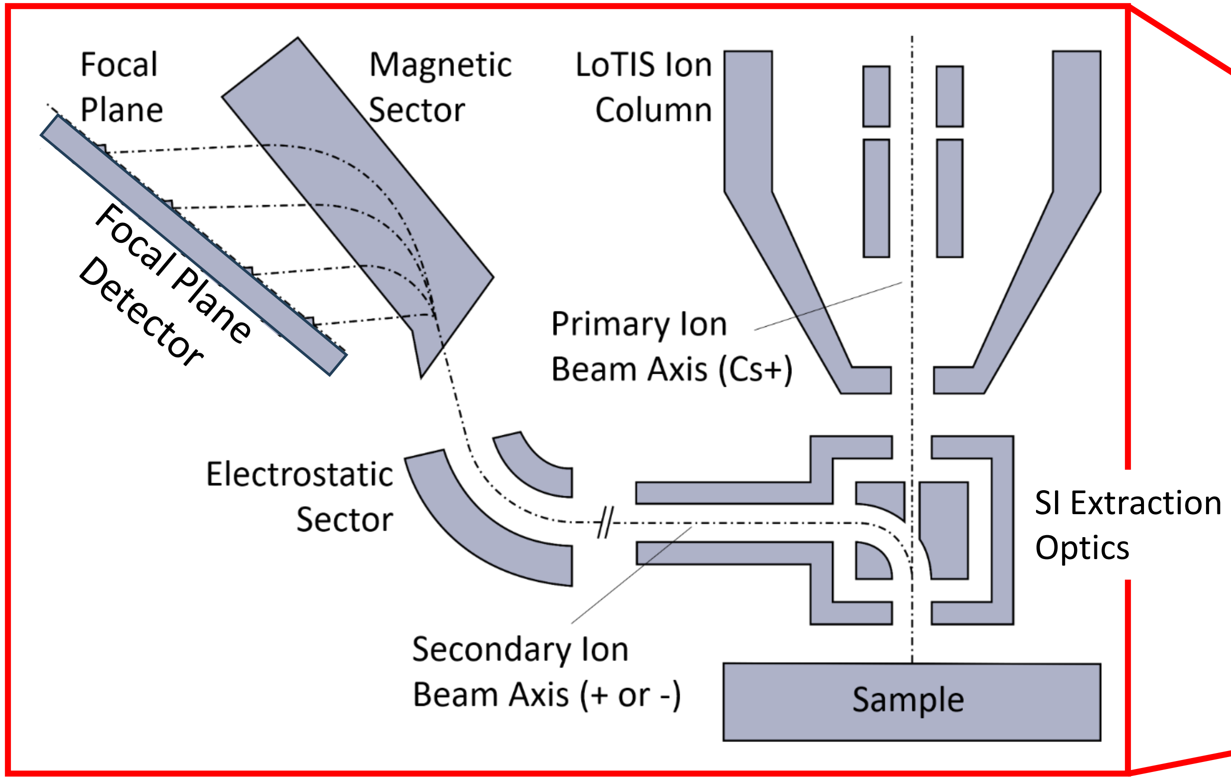
SIMS:ZERO

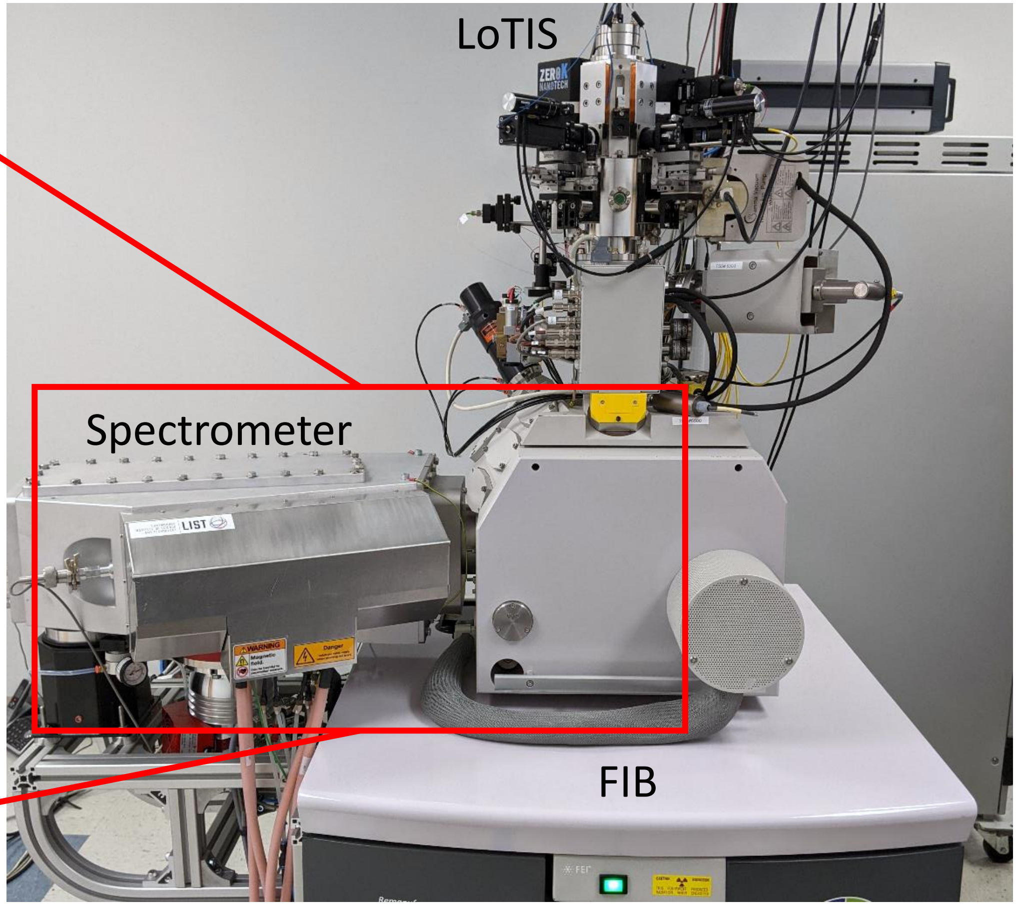
- Few-nanometer resolution (slide 21)
- High secondary ion yield (slides 23,24)
- Integrated sample-prep and analysis capability (slides 25-31)

SIMS:ZERO

Instrument Overview

Cs+ FIB:ZERO (zeroK) and SIMS spectrometer (LIST: Luxembourg Institute of Science and Technology) on a 600 series FIB (FEI)



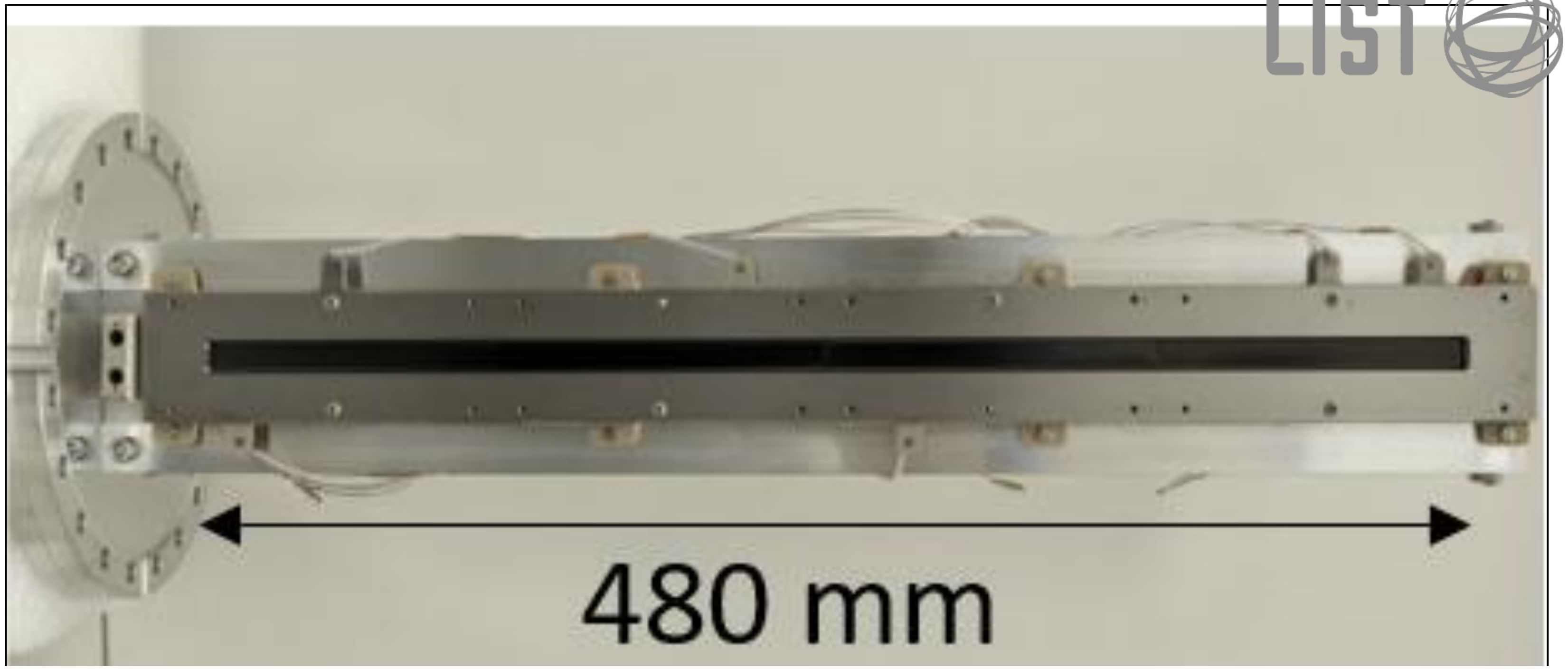


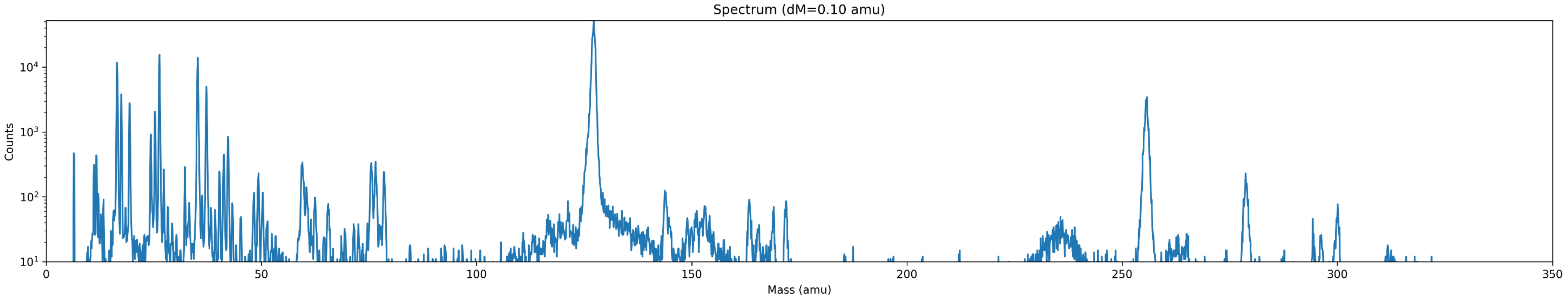
- FIB online 6/2020
- SIMS online 5/2021

Continuous Detector

- Sample the entire mass spectrum for every pixel (e.g. 6-350 amu)
- Collect the entire spectrum (as in ToF SIMS), but without painfully long acquisition times

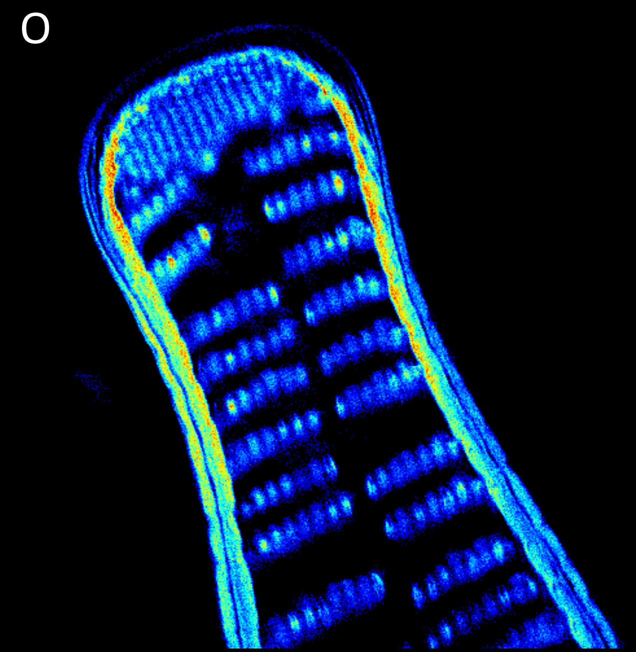
- 480 mm micro-channel plate
- Delay lines, discriminators allow for pulse counting along the full length

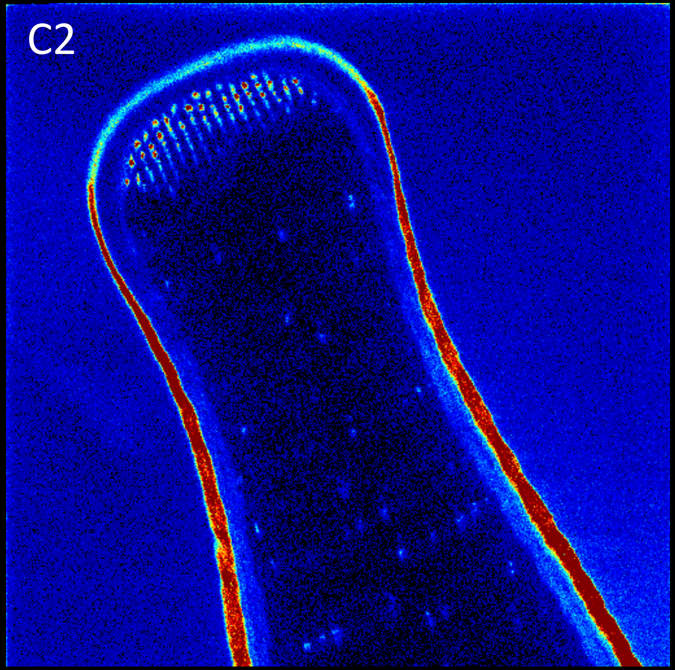


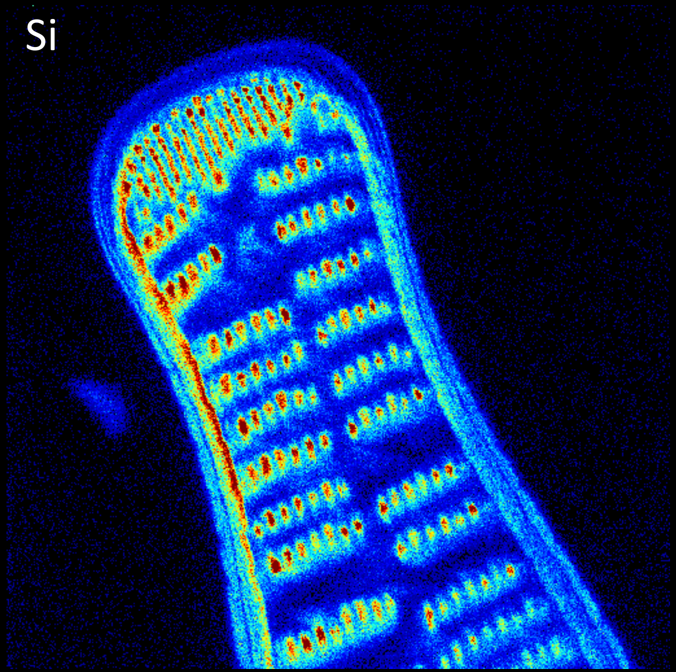


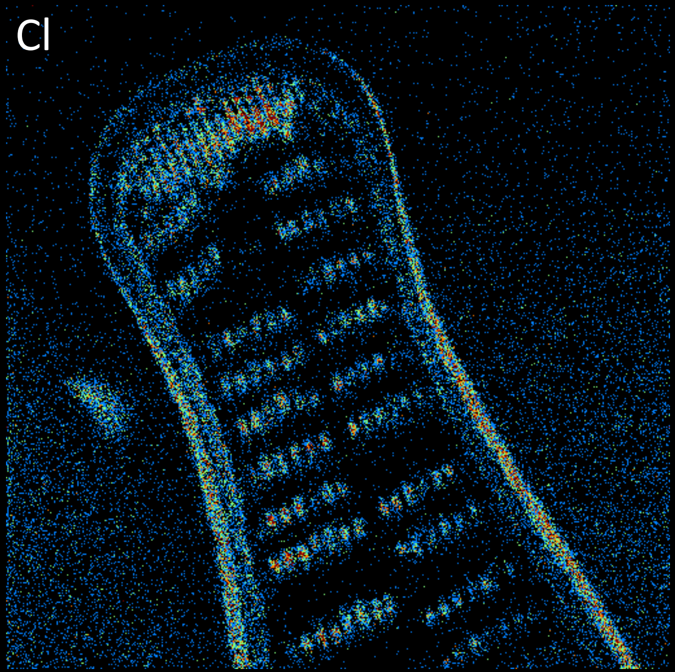
Diatoms
(Silica –shelled algae)

7.5 um FoV



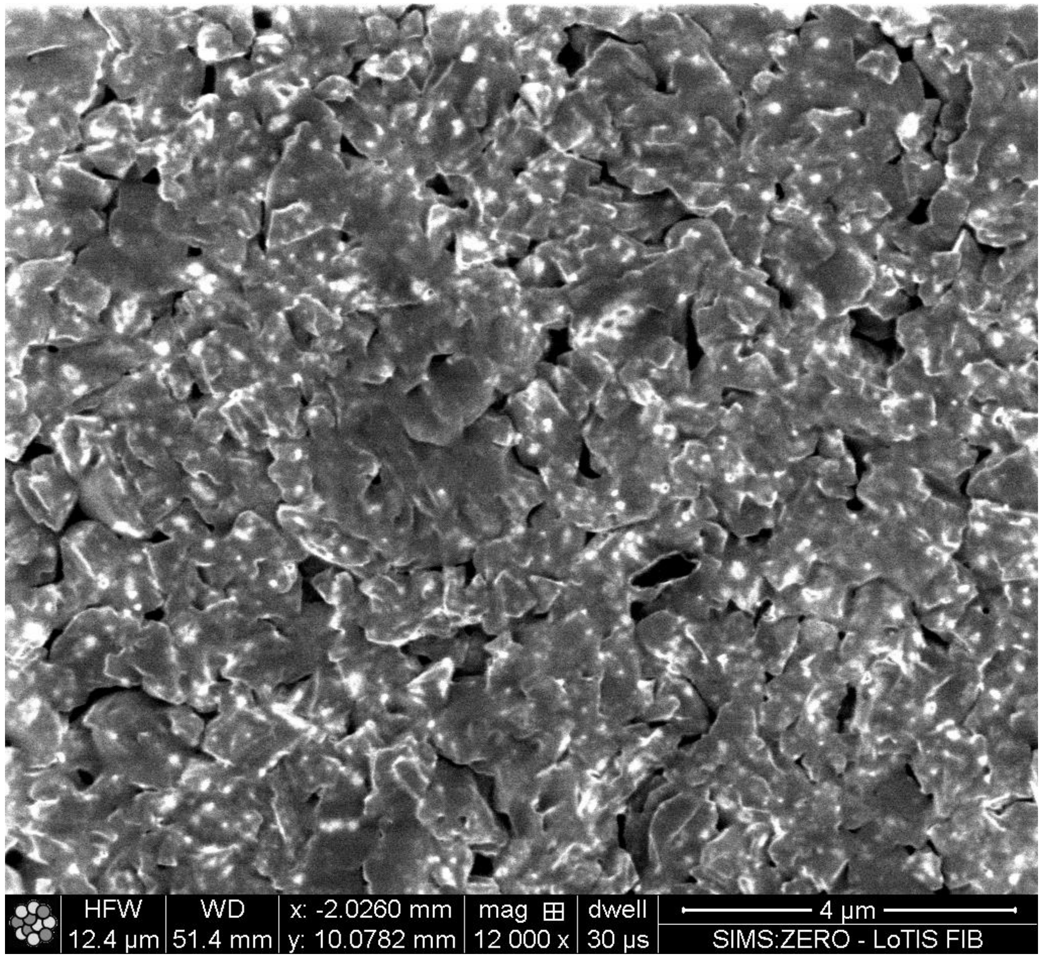






SIMS Analysis Example

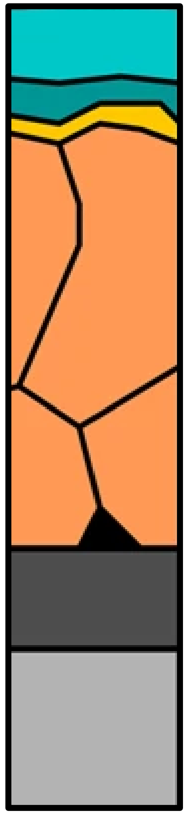
CIGS $Cu(In,Ga)Se_2$ – Rb doped



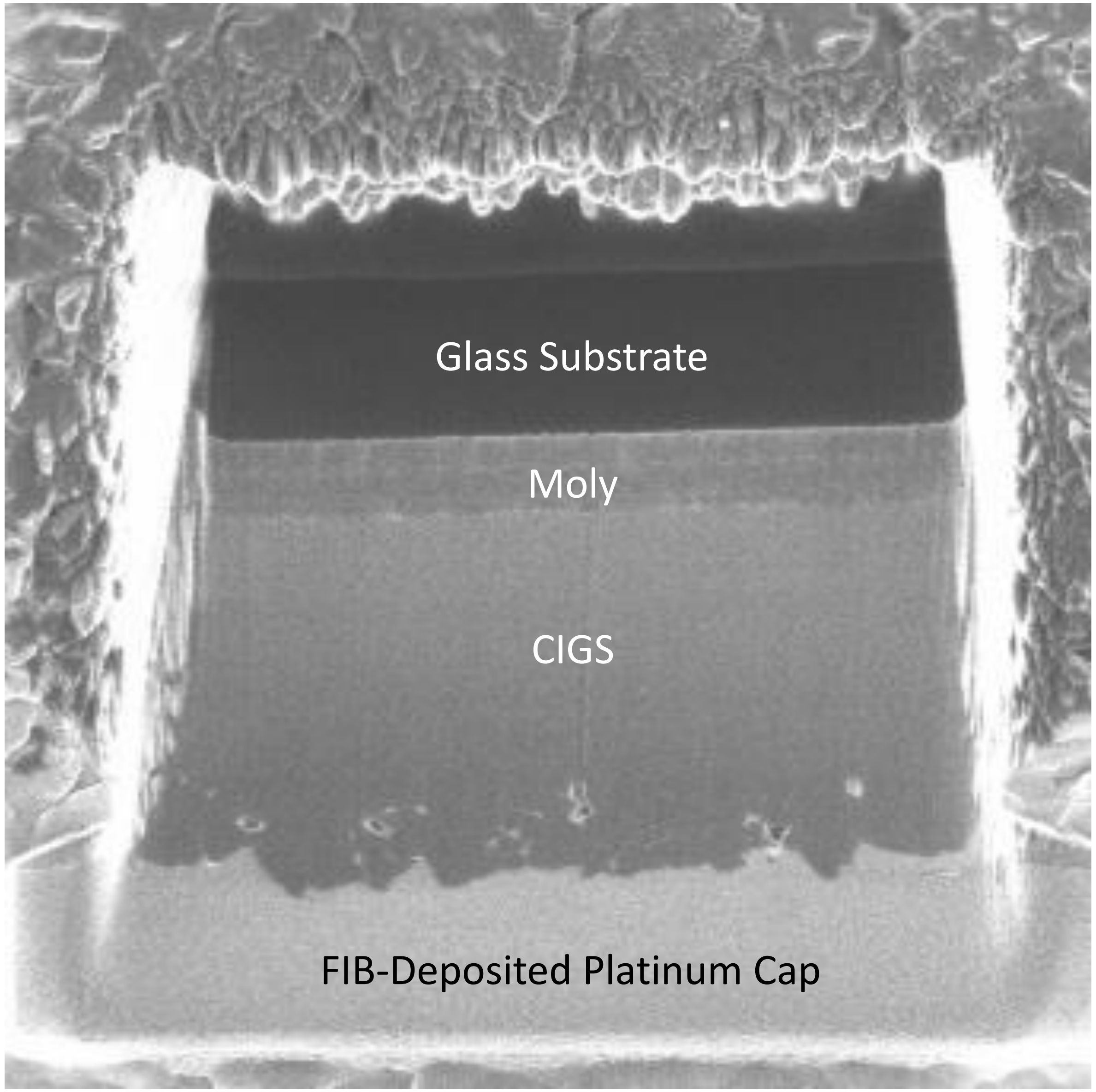
SE Image Cs+, 16keV, 10pA, 51.6mm WD

Summary

- CIGS is a solar cell absorber material
  - Rubidium doping increases conversion efficiency
- SIMS spectra clearly show all CIGS elements:
  - Cu, In, Ga, Rb in Positive Mode
  - Se in Negative Mode
- Secondary ion imaging channels show distribution of elements in sample, eg Rb dopants concentrated in grain boundaries
- Secondary electron images provide complementary information at high resolution
- Section view technique provides superior SIMS data

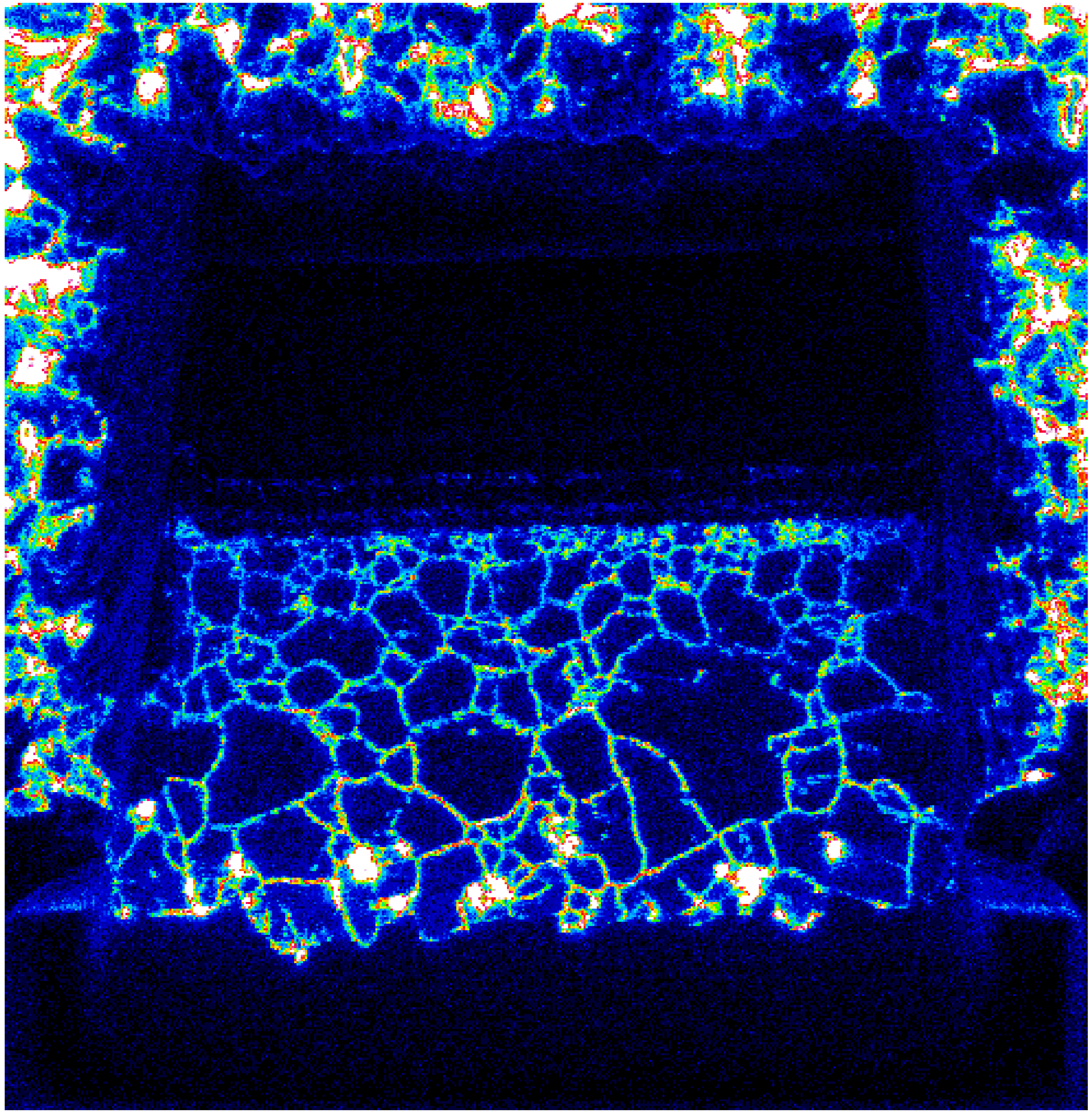


Werner, et al. *Scientific Reports* **volume 10**, 7530 (2020)



Secondary electron image

- Sample polished, ready for SIMS
- 9.5 µm FOV

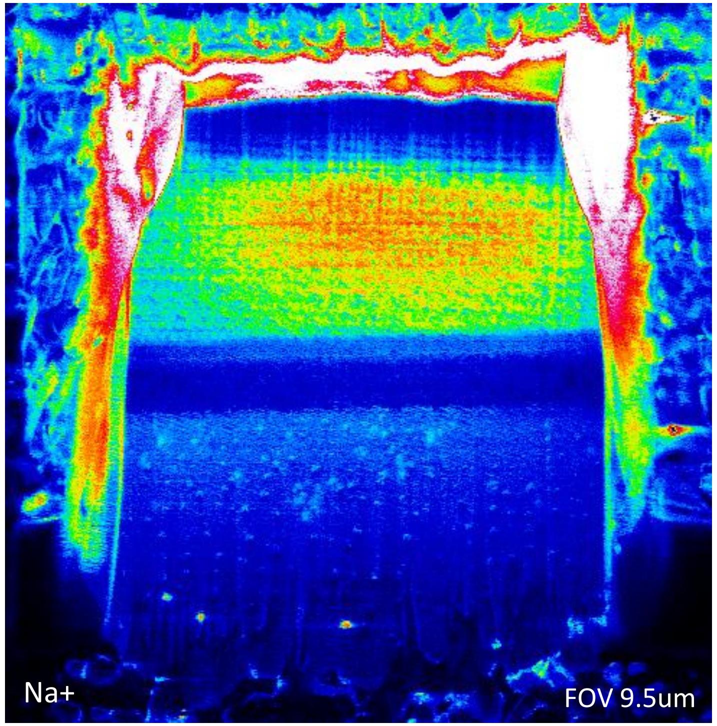


Rb$^+$ SIMS Image

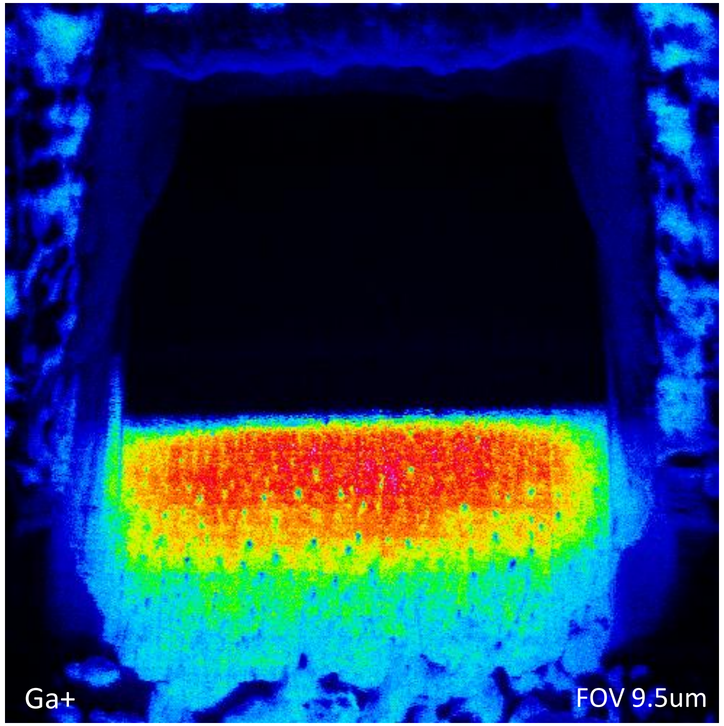
- Rb confined to grain boundaries
- Grains are smaller near the interfaces
- Bilayer structure in the Moly layer

CIGS $Cu(In,Ga)Se_2$ – Rb doped

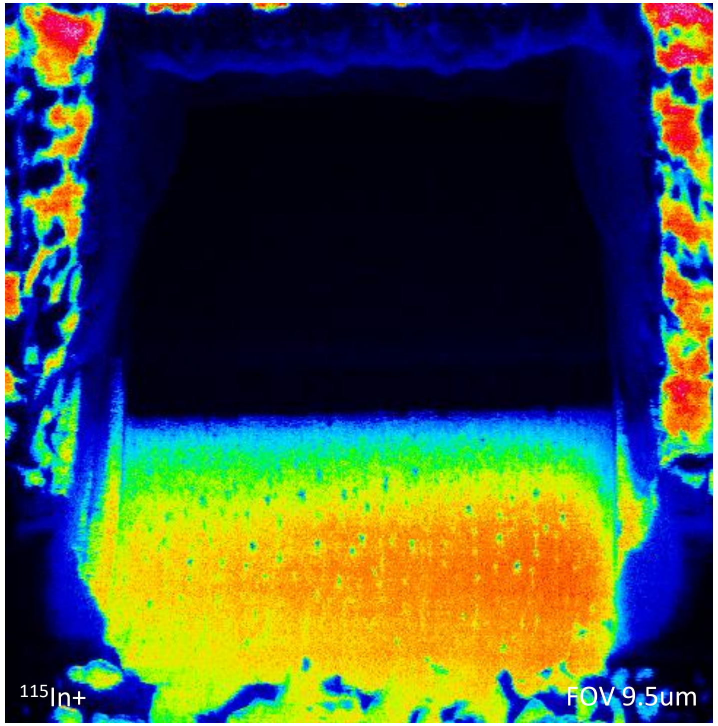
Section View – Positive Ions – Post 3rd Polish



Na – Soda Lime Glass



Ga concentration gradient ↑

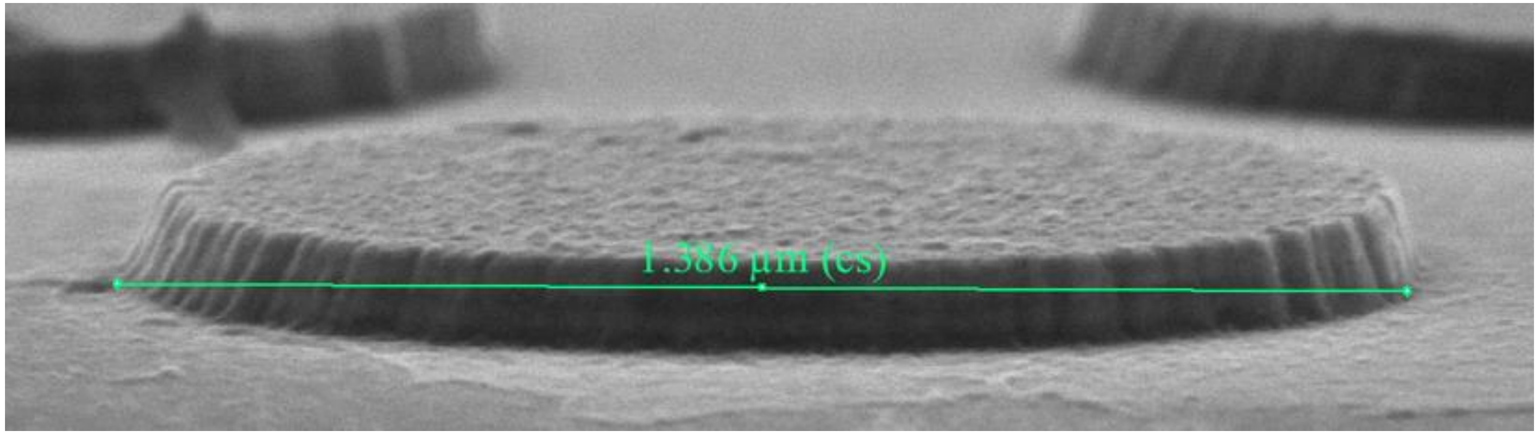


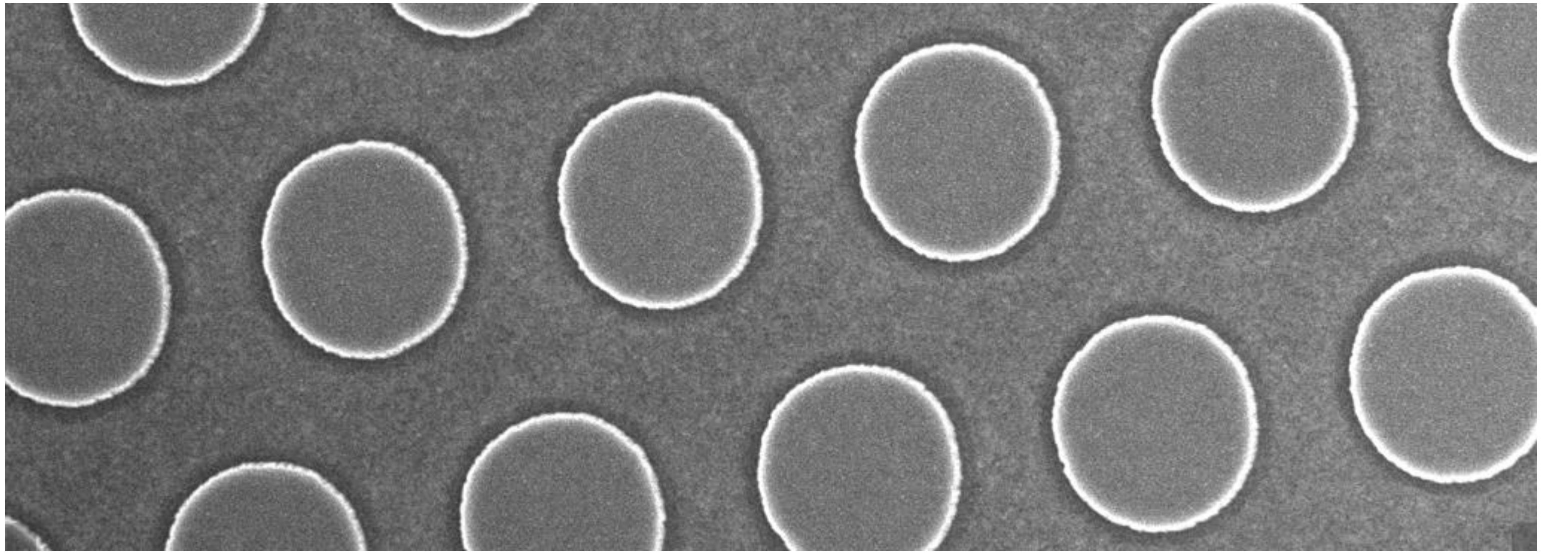
In concentration gradient ↓

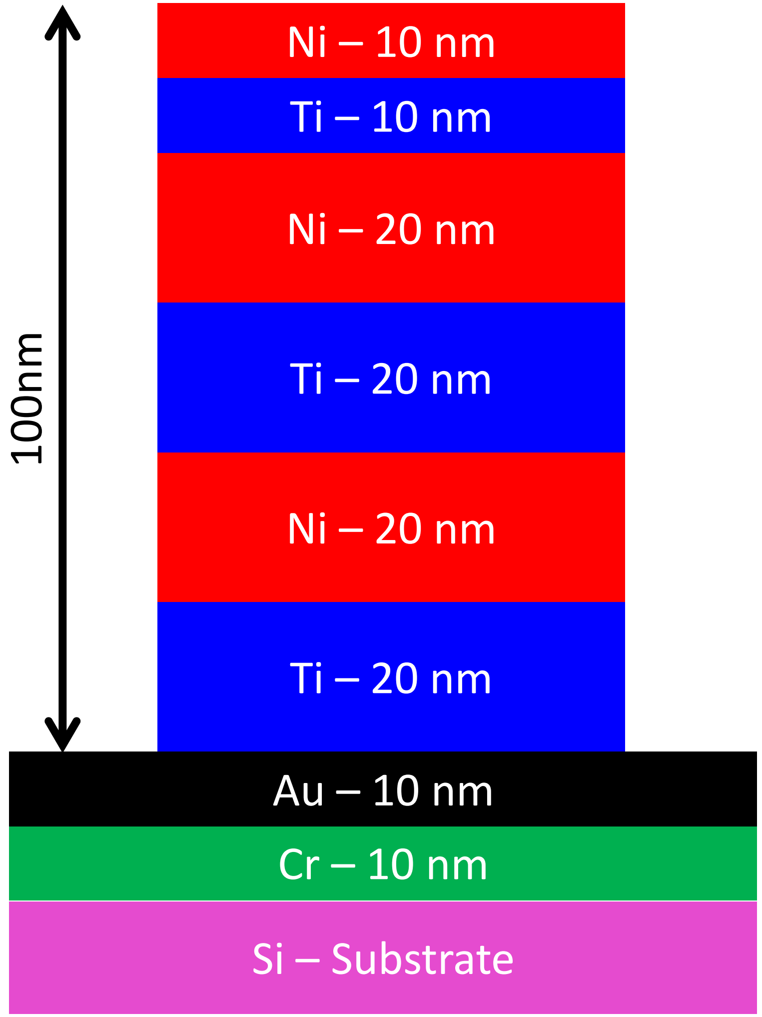
Cs+, 16keV, 10pA, 51.6mm WD
CIGS_Pos_2107201626359.csv

TiNi Pillars

Multilayer Ti / Ni Pillars on Au/Cr/Si Substrate

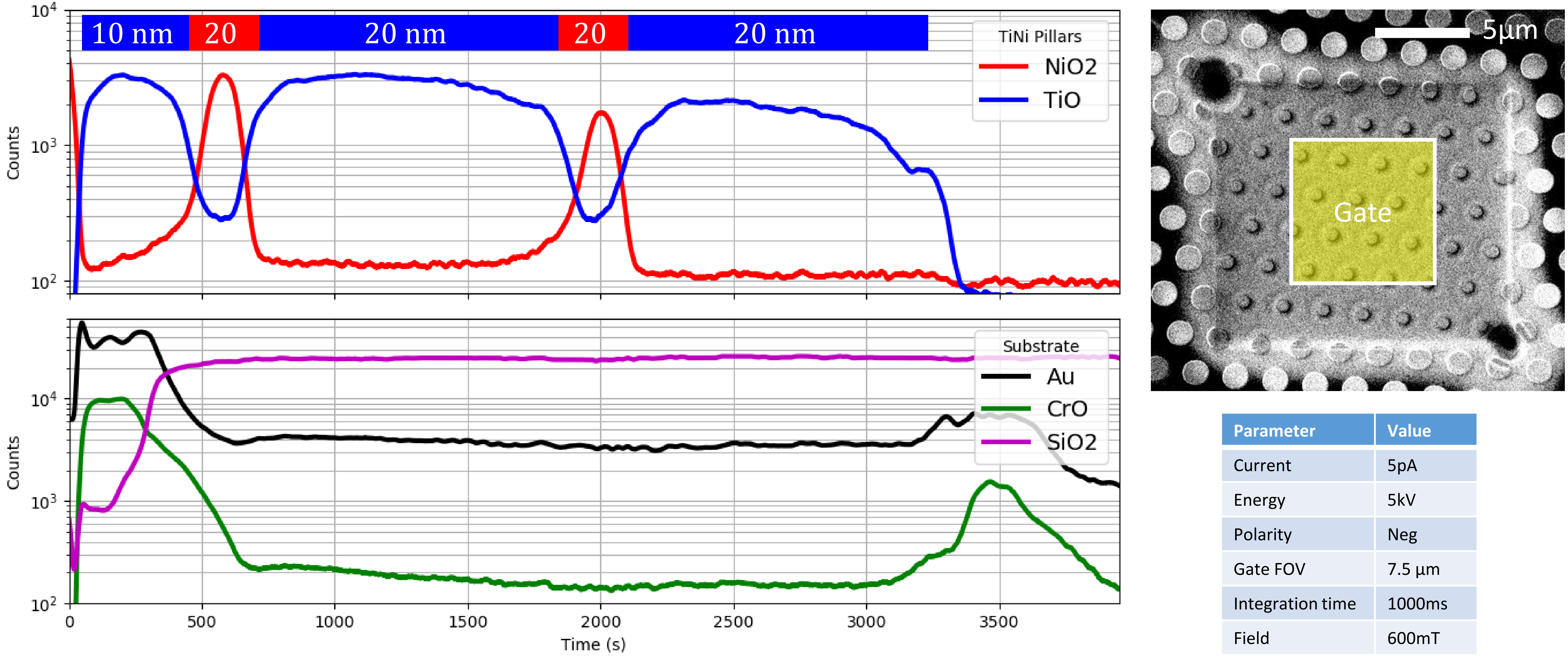






TiNi Pillars

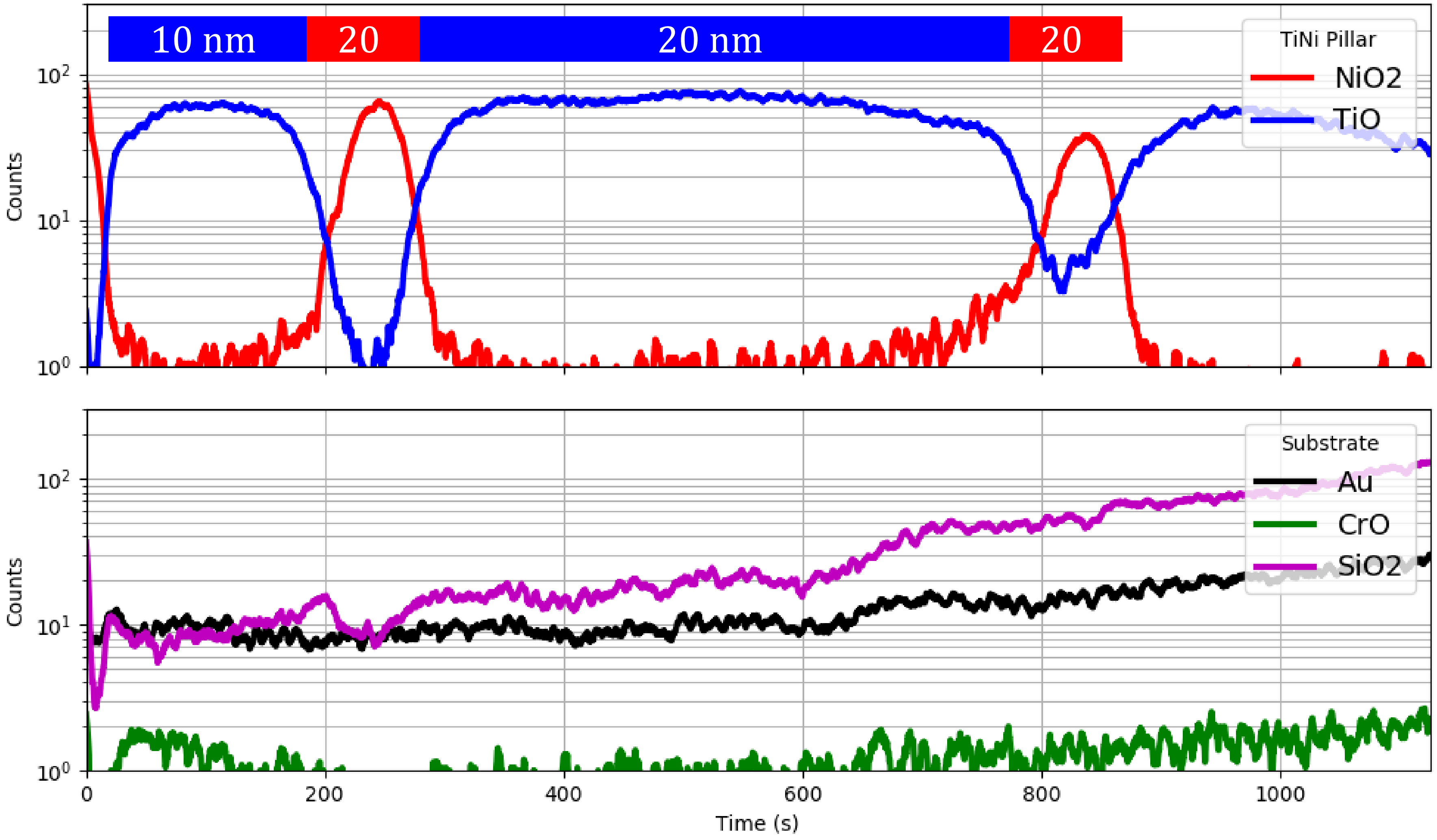
'Large' Area Depth Profile (7.5µm Gate)

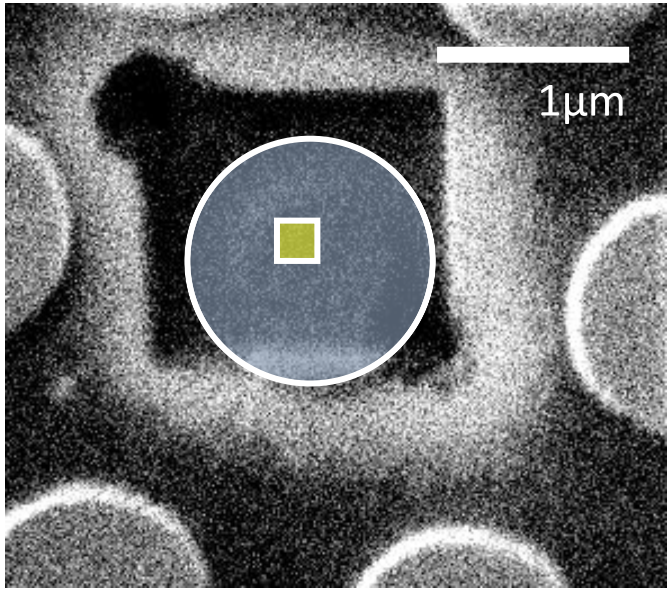


Parameter	Value
Current	5pA
Energy	5kV
Polarity	Neg
Gate FOV	7.5 µm
Integration time	1000ms
Field	600mT

TiNi Pillars

'Small' Area Depth Profile (200nm Gate)



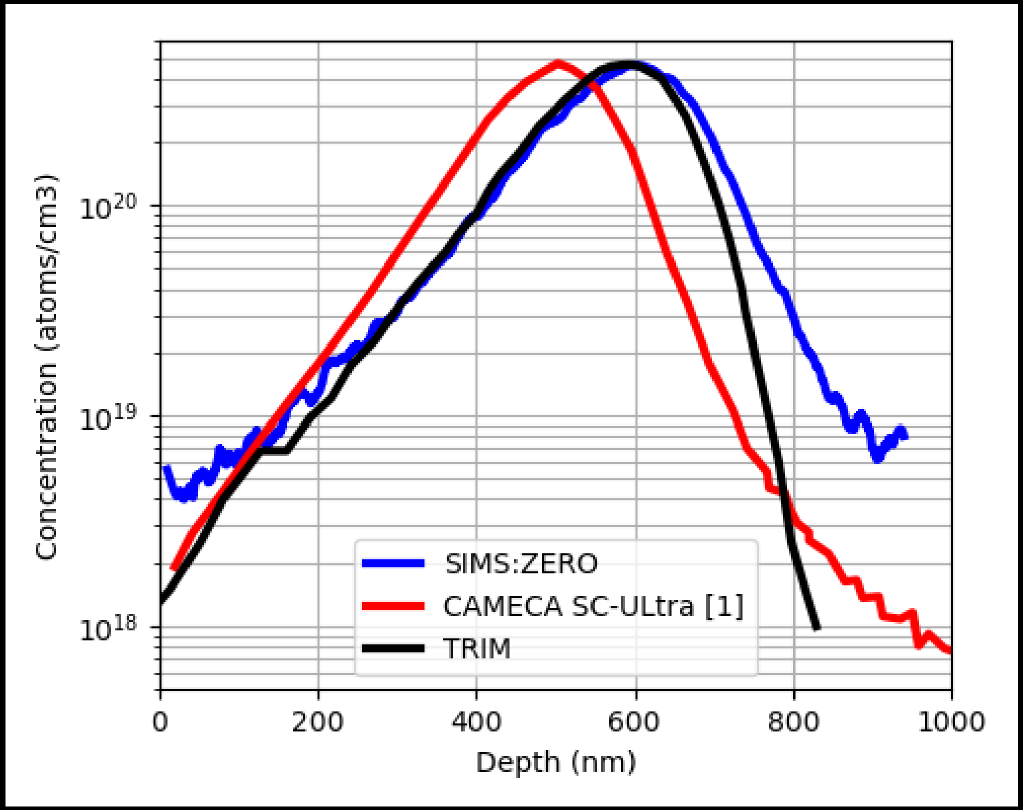


Parameter	Value
Current	2pA
Energy	5kV
Polarity	Neg
Gate FOV	200 nm
Integration time	250ms
Field	600mT

Boron Doped Silicon

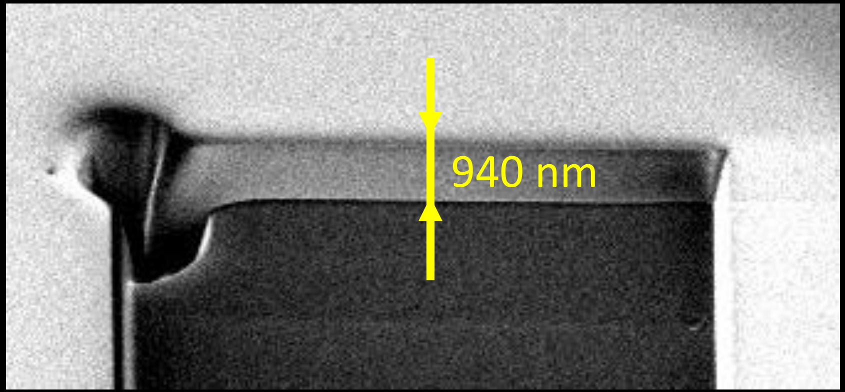
Depth Profile Comparison – Reference Sample

Implantation of B at 190 keV; Dose 10^{16} ions/cm^2



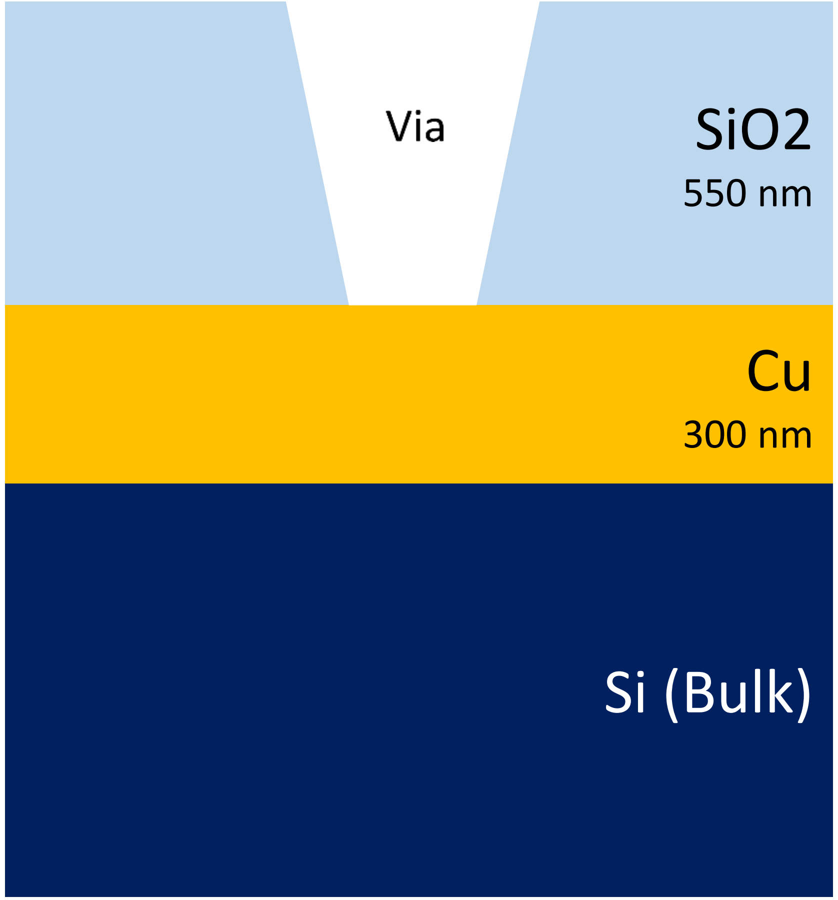
[1] Eswara, et al. MRS COMMINCATIONS. Volume 9, Issue 3 (2019) 10.1557/mrc.2019.89

	SIMS:ZERO	SC Ultra
Primary Ion	Cs^+	O_2^+
Energy	5kV	4.5kV
Current	25 pA	85000 pA
Area	4.2um x 4.2um	?
Polarity	Neg	Pos
Secondary Ion	BO2-	B+



Endpointing Example

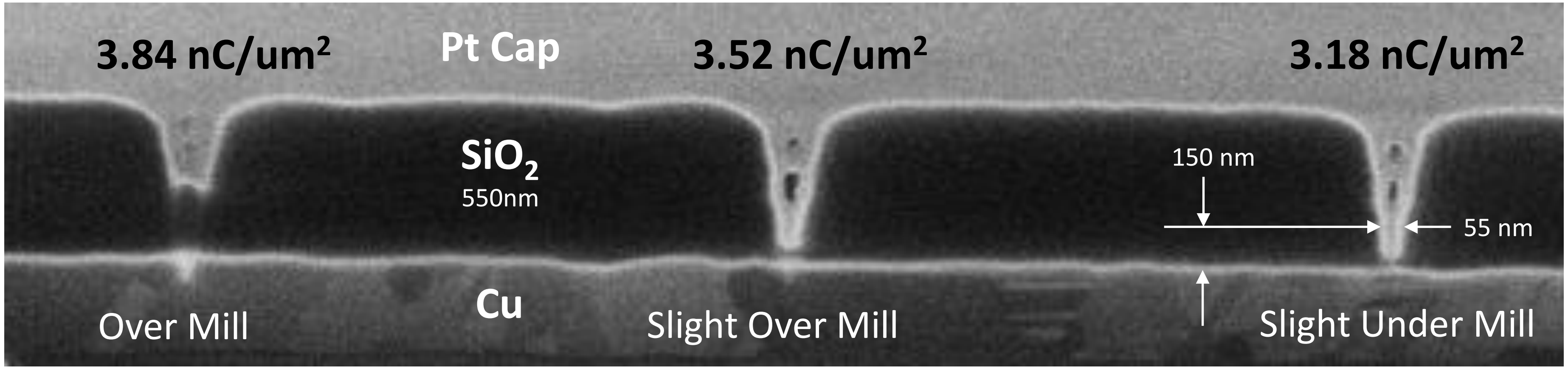
Test sample SiO_2 on Cu



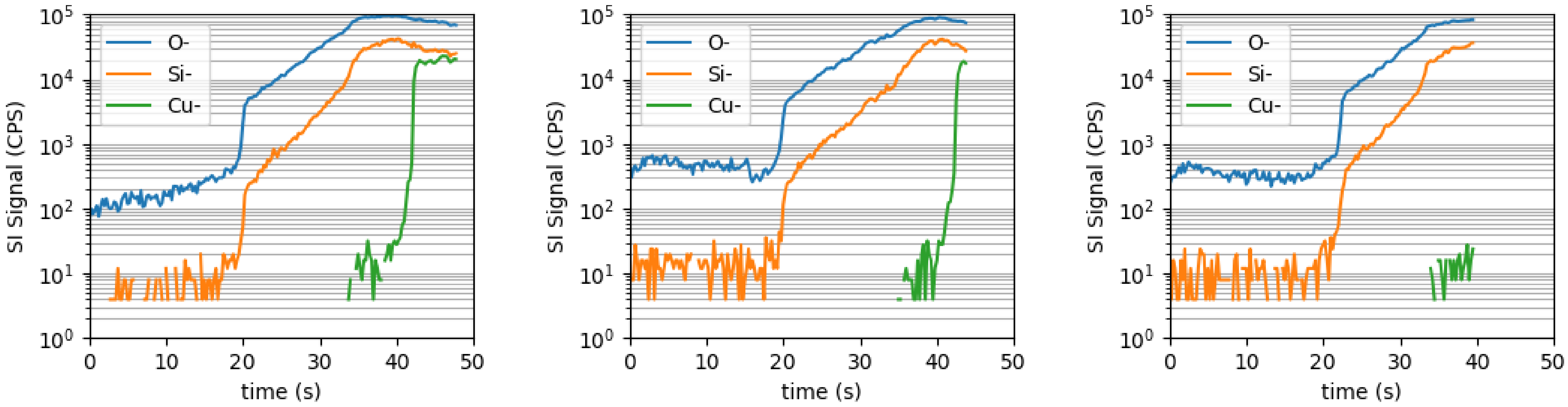
- Objective is to mill via through SiO_2 and stop when Cu is reached without over-milling
- Typically done by monitoring for a change in SE yield, but SE signal can be difficult to interpret
  - SE yield can change due to topography (sidewall), grounding (voltage), material contrast, etc
  - SNR, Contrast is very low for high aspect ratio vias
- Monitoring the Secondary Ion Signal on one or more elemental channels provides
  - Multiple signal channels for analysis
  - More definitive information, ie “Cu is Cu”, “Si is Si”, etc
  - High SNR, Contrast signals

Section View of 50nm Rectangular Vias

50nm x 500nm Mill box, 2.0 pA, 16 kV, 54 mm WD



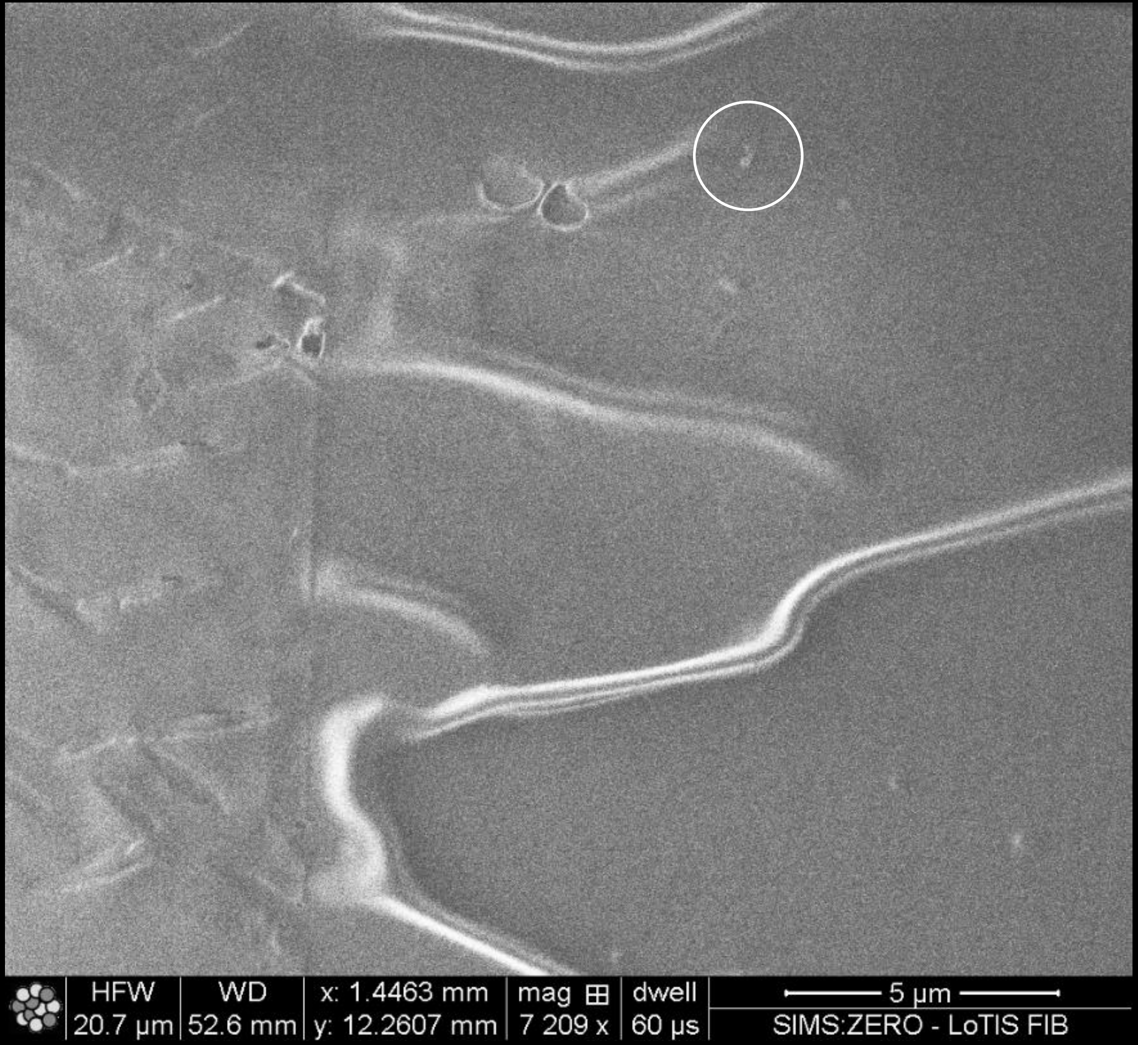
SIMS signals Predictive of Milling Results

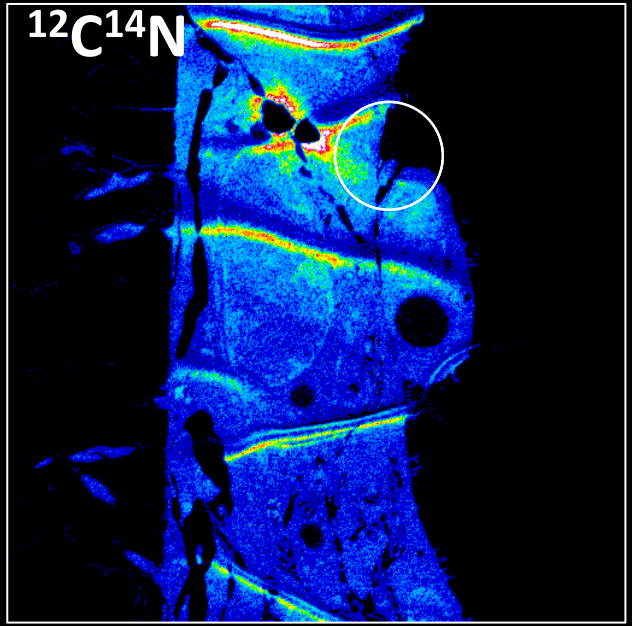


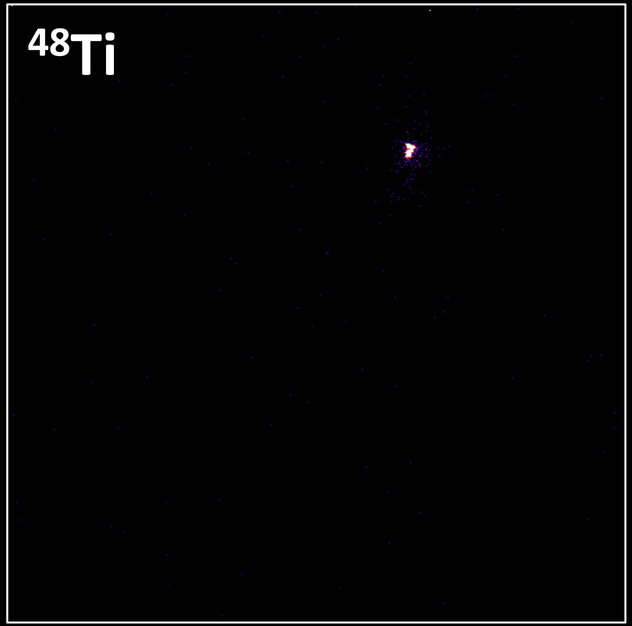
Signal Level Remains High Despite Higher Aspect Ratio

Needle in a haystack:

Find the TiO nanoparticle in
the huge, fixed cell







SUMMARY SIMS:ZERO

Strengths:

… has all the capabilities of FIB:ZERO

… adds high-resolution, high-sensitivity, high speed elemental analysis

… consider in lieu of EDX or ToF SIMS for analysis of complex, multi-element, or light element samples

… new opportunities for FIB beam control via SIMS signal

Weaknesses:

Lower mass-resolving power than most dedicated SIMS systems

Quantification of concentrations harder than EDX